8-bit Proprietary Microcontrollers

CMOS

F²MC-8FX MB95100AM Series

MB95108AM/F104AMS/F104ANS/F104AJS/F106AMS/F106ANS/F106AJS/ MB95F108AMS/F108ANS/F108AJS/F104AMW/F104ANW/F104AJW/F106AMW/ MB95F106ANW/F106AJW/F108AMW/F108ANW/F108AJW/FV100D-103

DESCRIPTION

The MB95100AM series is general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions.

Note : F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURE

- F²MC-8FX CPU core
 - Instruction set optimized for controllers
 - Multiplication and division instructions
 - 16-bit arithmetic operations
 - Bit test branch instruction
 - Bit manipulation instructions etc.
- Clock
 - Main clock
 - Main PLL clock
 - Sub clock (for dual clock product)
 - Sub PLL clock (for dual clock product)

(Continued)

Be sure to refer to the "Check Sheet" for the latest cautions on development.

"Check Sheet" is seen at the following support page

URL : http://www.fujitsu.com/global/services/microelectronics/product/micom/support/index.html

"Check Sheet" lists the minimal requirement items to be checked to prevent problems beforehand in system development.



- Timer
 - + 8/16-bit compound timer $\times\,2$ channels
 - 16-bit reload timer
 - 8/16-bit PPG $\times\,2$ channels
 - 16-bit PPG × 2 channels
 - Timebase timer
 - Watch prescaler (for dual clock product)
- LIN-UART
 - Full duplex double buffer
 - Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
- UART/SIO
 - Full duplex double buffer
 - Clock asynchronous (UART) or clock synchronous (SIO) serial data transfer capable
- I²C*
 - Built-in wake-up function
- External interrupt
 - Interrupt by edge detection (rising, falling, or both edges can be selected)
 - Can be used to recover from low-power consumption (standby) modes.
- 8/10-bit A/D converter
 - 8-bit or 10-bit resolution can be selected
- Low-power consumption (standby) mode
 - Stop mode
 - Sleep mode
 - Watch mode (for dual clock product)
 - Timebase timer mode
- I/O ports :
 - The number of maximum ports
 - Single clock product : 54 ports
 - Dual clock product : 52 ports
 - Port configuration
 - General-purpose I/O ports (N-ch open drain) : 6 ports
 - General-purpose I/O ports (CMOS)
- : Single clock product : 48 ports
 - Dual clock product : 46 ports
- Programmable input voltage levels of port Automotive input level / CMOS input level / hysteresis input level
- Flash memory security function Protects the content of Flash memory (Flash memory device only)
- * : Purchase of Fujitsu I²C components conveys a license under the Philips I²C Patent Rights to use, these components in an I²C system provided that the system conforms to the I²C Standard Specification as defined by Philips.

■ MEMORY LINEUP

	Flash	RAM
MB95F104AMS/F104ANS/F104AJS	16K bytes	512 bytes
MB95F104AMW/F104ANW/F104AJW	Torc bytes	512 byles
MB95F106AMS/F106ANS/F106AJS	32K bytes	1K byte
MB95F106AMW/F106ANW/F106AJW	SZR Dytes	TK byle
MB95F108AMS/F108ANS/F108AJS	60K bytes	0K bytee
MB95F108AMW/F108ANW/F108AJW	60K bytes	2K bytes

■ PRODUCT LINEUP

Pa	Part number	MB95 108AM	MB95F 104AMS/ MB95F 106AMS/ MB95F 108AMS	MB95F 104ANS/ MB95F 106ANS/ MB95F 108ANS	MB95F 104AMW/ MB95F 106AMW/ MB95F 108AMW	MB95F 104ANW/ MB95F 106ANW/ MB95F 108ANW	MB95F 104AJS/ MB95F 106AJS/ MB95F 108AJS	MB95F 104AJW/ MB95F 106AJW/ MB95F 108AJW
Ту	ре	MASK ROM product			Flash men	nory product		
RC	DM capacity*1		60 Kbytes (Max)					
RA	M capacity*1			2	Kbytes (Ma	x)		
Re	eset output			Yes			N	0
Option*2	Clock system	Selectable single/dual clock*3	Singl	e clock	Dual	clock	Single clock	Dual clock
Opti	Low voltage detection reset	Yes/No	No	Yes	No		Yes	
	Clock supervisor			No			Ye	es
CF	PU functions	Interrupt proc	t length ngth th truction exec cessing time	: 8 : 1 : 1 : 1 : 0 : 0	bits to 3 bytes , 8, and 16 b 1.5 ns (at ma .6 μs (at mag	achine clock chine clock f	frequency 16. requency 16.2 OS : 48 ports)	5 MHz)
	General-pur- pose I/O ports	 Dual clock Programmab 	product : 52 le input volta	ports (N-ch o age levels of p evel / CMOS ir	pen drain : 6 port :	ports, CMC	S : 46 ports)	
	Timebase timer	Interrupt cycl	e : 0.5 ms, 2	.1 ms, 8.2 ms	, 32.8 ms (a	t main oscilla	ation clock 4 N	(Hz)
ctions	Watchdog timer	Reset genera At main oscil At sub oscilla	lation clock 1	10 MHz 2.768 kHz (for	dual clock p		n 105 ms in 250 ms	
fun	Wild register	Capable of re	eplacing 3 by	tes of ROM o	lata			
Peripheral fun	l ² C	Detecting tra	nction and arl nsmitting dire on repeated g	d receiving bitration funct ection function generation an	n	unctions		
	UART/SIO	NRZ type tra LSB-first or N	ouble buffer, nsfer format, /ISB-first can	variable data , error detecte) be selected.	d function		-in baud rate ç I data transfer	

	Part number	MB95 108AM	MB95F 104AMS/ MB95F 106AMS/ MB95F	MB95F 104ANS/ MB95F 106ANS/ MB95F	MB95F 104AMW/ MB95F 106AMW/ MB95F	MB95F 104ANW/ MB95F 106ANW/ MB95F	MB95F 104AJS/ MB95F 106AJS/ MB95F	MB95F 104AJW/ MB95F 106AJW/ MB95F
Par	ameter		108AMS	108ANS	108AMW	108ANW	108AJS	108AJW
	LIN-UART	Dedicated relo Full duplex do Clock asynchi ble LIN functions	uble buffer ronous (UAI	RT) or clock	synchronou	us (SIO) se		
	8/10-bit A/D converter (12 channels)	8-bit or 10-bit resolution can be selected.						
	16-bit reload timer	Two clock modes and two counter operating modes can be selected. Square w form output Count clock : 7 internal clocks and external clock can be selected. Counter operating mode : reload mode or one-shot mode can be selected.						
Ictions	8/16-bit compound timer (2 channels)			function, ar				
Peripheral functions	16-bit PPG (2 channels)	PWM mode o Counter opera Support for ex	ating clock :	8 selectable		ces		
Peri	8/16-bit PPG (2 channels)	Each channel 1 channel". Counter opera					nnels" or "16	ô-bit PPG ×
	Watch counter (for dual clock product)	Count clock : Counter value selecting cloc	can be set	from 0 to 6	3. (Capable	of counting	for 1 minute	
	Watch prescaler (for dual clock product)	4 selectable ir	nterval times	s (125 ms, 2	250 ms, 500	ms, or 1 s)		
	External interrupt (12 channels)	Interrupt by ea Can be used t				n edges can	be selected	l.)
	Flash memory	Supports auto Write/Erase/E A flag indicatin Number of wri Data retention Erase can be Block protection Flash Security (MB95F108A	rase-Suspe ng completion (te/erase cyonomic time : 20 y performed of on with extend r Feature fo	nd/Resume on of the alo cles (Minim ears on each blo ernal progra r protecting	e commands gorithm um) : 10000 ck mming volta the content	times ge of the Flash		only)
Sta	ndby mode	Sleep, stop, w	atch (for du	al clock pro	duct), and t	timebase tin	ner	

- *1 : For ROM capacity and RAM capacity, refer to "■ MEMORY LINEUP".
- *2 : For details of option, refer to "■ MASK OPTION".
- *3 : Specify clock mode when ordering MASK ROM.
- *4 : Embedded Algorithm is a trade mark of Advanced Micro Devices Inc.
- Note : Part number of the evaluation product in MB95100AM series is MB95FV100D-103. When using it, the MCU board (MB2146-303A) is required.

■ OSCILLATION STABILIZATION WAIT TIME

The initial value of the main clock oscillation stabilization wait time is fixed to the maximum value. The maximum value is shown as follows.

Oscillation stabilization wait time	Remarks
(214-2) / Есн	Approx. 4.10 ms (at main oscillation clock 4 MHz)

■ PACKAGES AND CORRESPONDING PRODUCTS

Part number Parameter	MB95108AM	MB95F104AMS/F104ANS/ F104AJS MB95F106AMS/F106ANS/ F106AJS MB95F108AMS/F108ANS/ F108AJS	MB95F104AMW/F104ANW/ F104AJW MB95F106AMW/F106ANW/ F106AJW MB95F108AMW/F108ANW/ F108AJW	MB95FV100D-103
FPT-64P-M03	0	0	0	×
FPT-64P-M09	0	0	0	×
BGA-224P- M08	Х	×	×	0

 \bigcirc : Available

 $\times\,$: Unavailable

■ DIFFERENCES AMONG PRODUCTS AND NOTES ON SELECTING PRODUCTS

• Notes on Using Evaluation Products

The Evaluation product has not only the functions of the MB95100AM series but also those of other products to support software development for multiple series and models of the F²MC-8FX family. The I/O addresses for peripheral resources not used by the MB95100AM series are therefore access-barred. Read/write access to these access-barred addresses may cause peripheral resources supposed to be unused to operate, resulting in unexpected malfunctions of hardware or software.

Particularly, do not use word access to odd numbered byte address in the prohibited areas (If these access are used, the address may be read or write unexpectedly).

Also, as the read values of prohibited addresses on the evaluation product are different to the values on the flash memory and MASK ROM products, do not use these values in the program.

The Evaluation product do not support the functions of some bits in single-byte registers. Read/write access to these bits does not cause hardware malfunctions. Since the Evaluation, Flash memory, and MASK ROM products are designed to behave completely the same way in terms of hardware and software.

• Difference of Memory Spaces

If the amount of memory on the Evaluation product is different from that of the Flash memory or MASK ROM product, carefully check the difference in the amount of memory from the model to be actually used when developing software.

For details of memory space, refer to "■ CPU CORE".

• Current Consumption

The current consumption of Flash memory product is typically greater than for MASK ROM product.

For details of current consumption, refer to "■ ELECTRICAL CHARACTERISTICS".

Package

For details of information on each package, refer to "■ PACKAGES AND CORRESPONDING PRODUCTS" and "■ PACKAGE DIMENSIONS".

Operating Voltage

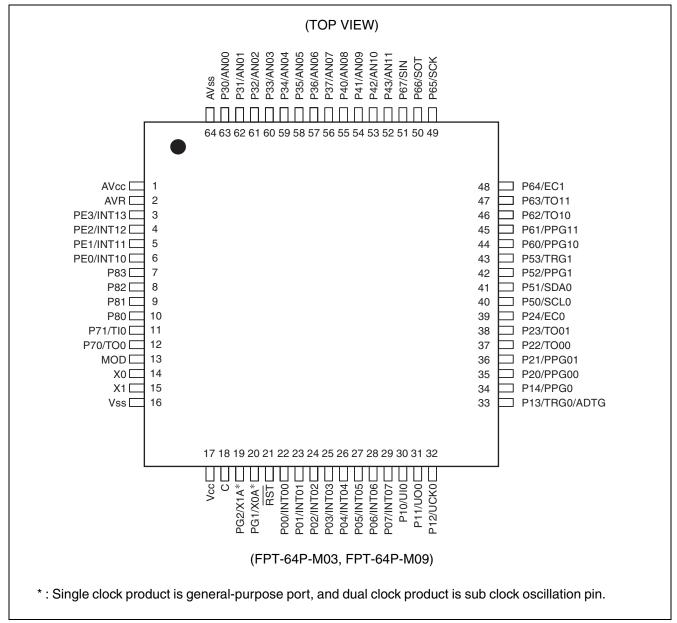
The operating voltage are different among the Evaluation, Flash memory, and MASK ROM products.

For details of operating voltage, refer to "■ ELECTRICAL CHARACTERISTICS".

• Difference between RST and MOD Pins

The $\overline{\text{RST}}$ and MOD pins are hysteresis inputs on the MASK ROM product. A pull-down resistor is provided for the MOD pin of the MASK ROM product.

■ PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin no.	Pin name	I/O Circuit type*	Function		
1	AVcc	_	A/D converter power supply pin		
2	AVR	_	A/D converter reference input pin		
3	PE3/INT13				
4	PE2/INT12	Р	P General-purpose I/O port. The pins are shared with the external interrupt input.		
5	PE1/INT11	Г			
6	PE0/INT10				
7	P83				
8	P82	0	Conevel numero I/O port		
9	P81	0	O General-purpose I/O port		
10	P80				
11	P71/TI0		General-purpose I/O port. The pin is shared with 16-bit reload timer ch.0 output.		
12	P70/TO0	Н	General-purpose I/O port. The pin is shared with 16-bit reload timer ch.0 input.		
13	MOD	В	An operating mode designation pin		
14	X0	^	Main clock input oscillation pin		
15	X1	A	Main clock input/output oscillation pin		
16	Vss		Power supply pin (GND)		
17	Vcc		Power supply pin		
18	С		Capacitor connection pin		
19	PG2/X1A	H/A	Single clock product is general-purpose port (PG2) . Dual clock product is sub clock input/output oscillation pin (32 kHz).		
20	PG1/X0A	Π/A	Single clock product is general-purpose port (PG1) . Dual clock product is sub clock input oscillation pin (32 kHz).		
21	RST	B'	Reset pin		
22	P00/INT00				
23	P01/INT01				
24	P02/INT02				
25	P03/INT03	С	General-purpose I/O port.		
26	P04/INT04	U	The pins are shared with external interrupt input. Large current port.		
27	P05/INT05				
28	P06/INT06				
29	P07/INT07				
30	P10/UI0	G	General-purpose I/O port. The pin is shared with UART/SIO ch.0 data input.		

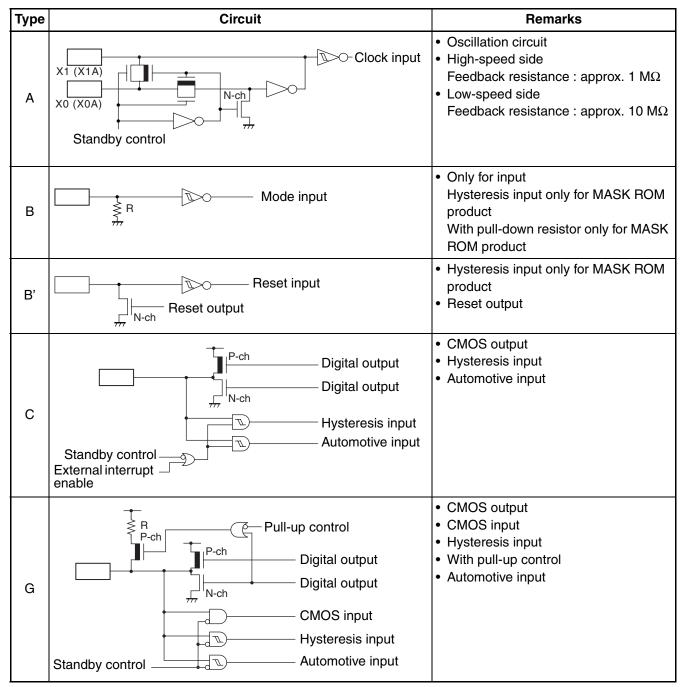
Pin no.	Pin name	I/O Circuit type*	Function
31	P11/UO0		General-purpose I/O port. The pin is shared with UART/SIO ch.0 data output.
32	P12/UCK0		General-purpose I/O port. The pin is shared with UART/SIO ch.0 clock I/O.
33	P13/TRG0/ ADTG	Н	General-purpose I/O port. The pin is shared with 16-bit PPG ch.0 trigger input (TRG0) and A/D trigger input (ADTG).
34	P14/PPG0		General-purpose I/O port. The pin is shared with 16-bit PPG ch.0 output.
35	P20/PPG00		General-purpose I/O port.
36	P21/PPG01		The pins are shared with 8/16-bit PPG ch.0 output.
37	P22/TO00	н	General-purpose I/O port.
38	P23/TO01		The pins are shared with 8/16-bit compound timer ch.0 output.
39	P24/EC0		General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch.0 clock input.
40	P50/SCL0		General-purpose I/O port. The pin is shared with I ² C ch.0 clock I/O.
41	P51/SDA0		General-purpose I/O port. The pin is shared with I ² C ch.0 data I/O.
42	P52/PPG1	н	General-purpose I/O port. The pin is shared with 16-bit PPG ch.1 output.
43	P53/TRG1		General-purpose I/O port. The pin is shared with 16-bit PPG ch.1 trigger input.
44	P60/PPG10		General-purpose I/O port.
45	P61/PPG11		The pins are shared with 8/16-bit PPG ch.1 output.
46	P62/TO10		General-purpose I/O port.
47	P63/TO11		The pins are shared with 8/16-bit compound timer ch.1 output.
48	P64/EC1	К	General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch.1 clock input.
49	P65/SCK		General-purpose I/O port. The pin is shared with LIN-UART clock I/O.
50	P66/SOT		General-purpose I/O port. The pin is shared with LIN-UART data output.
51	P67/SIN	L	General-purpose I/O port. The pin is shared with LIN-UART data input.
52	P43/AN11		
53	P42/AN10		General-purpose I/O port.
54	P41/AN09	J	The pins are shared with A/D converter analog input.
55	P40/AN08		

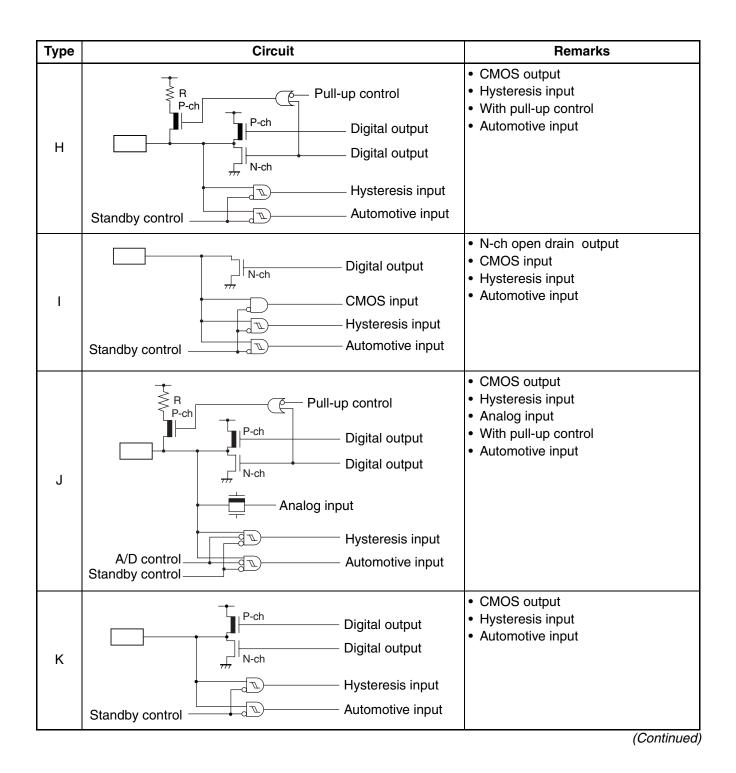
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Pin no.	Pin name	I/O Circuit type*	Function
56	P37/AN07		
57	P36/AN06	1	General-purpose I/O port. The pins are shared with A/D converter analog input.
58	P35/AN05	1	
59	P34/AN04	1 .	
60	P33/AN03	- J	
61	P32/AN02	1	
62	P31/AN01	1	
63	P30/AN00	1	
64	AVss		A/D converter power supply pin (GND)

*: For the I/O circuit type, refer to "■ I/O CIRCUIT TYPE"

■ I/O CIRCUIT TYPE





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(Contii	,	
Туре	Circuit	Remarks
L	CMOS input	 CMOS output CMOS input Hysteresis input Automotive input
	Standby control	
	Digital output	 N-ch open drain output Hysteresis input Automotive input
0	Standby control	
Р	R P-ch P-ch P-ch Digital output Digital output Digital output Hysteresis input Automotive input	 CMOS output Hysteresis input With pull-up control Automotive input
	External	

HANDLING DEVICES

• Preventing Latch-up

Care must be taken to ensure that maximum voltage ratings are not exceeded when they are used.

Latch-up may occur on CMOS ICs if voltage higher than V_{cc} or lower than V_{ss} is applied to input and output pins other than medium- and high-withstand voltage pins or if higher than the rating voltage is applied between V_{cc} pin and V_{ss} pin.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements.

Also, take care to prevent the analog power supply voltage (AVcc, AVR) and analog input voltage from exceeding the digital power supply voltage (Vcc) when the analog system power supply is turned on or off.

• Stable Supply Voltage

Supply voltage should be stabilized.

A sudden change in power-supply voltage may cause a malfunction even within the guaranteed operating range of the Vcc power-supply voltage.

For stabilization, in principle, keep the variation in Vcc ripple (p-p value) in a commercial frequency range (50 Hz/60 Hz) not to exceed 10% of the standard Vcc value and suppress the voltage variation so that the transient variation rate does not exceed 0.1 V/ms during a momentary change such as when the power supply is switched.

• Precautions for Use of External Clock

Even when an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from sub clock mode or stop mode.

■ PIN CONNECTION

• Treatment of Unused Input Pin

Leaving unused input pins unconnected can cause abnormal operation or latch-up, leaving to permanent damage. Unused input pins should always be pulled up or down through resistance of at least 2 k Ω . Any unused input/output pins may be set to output mode and left open, or set to input mode and treated the same as unused input pins. If there is unused output pin, make it to open.

• Treatment of Power Supply Pins on A/D Converter

Connect to be $AV_{CC} = V_{CC}$ and $AV_{SS} = AVR = V_{SS}$ even if the A/D converter is not in use.

Noise riding on the AV_{CC} pin may cause accuracy degradation. So, connect approx. 0.1 μ F ceramic capacitor as a bypass capacitor between AV_{CC} and AV_{ss} pins in the vicinity of this device.

• Power Supply Pins

In products with multiple V_{cc} or V_{ss} pins, the pins of the same potential are internally connected in the device to avoid abnormal operations including latch-up. However, you must connect the pins to external power supply and a ground line to lower the electro-magnetic emission level, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Moreover, connect the current supply source with the Vcc and Vss pins of this device at the low impedance.

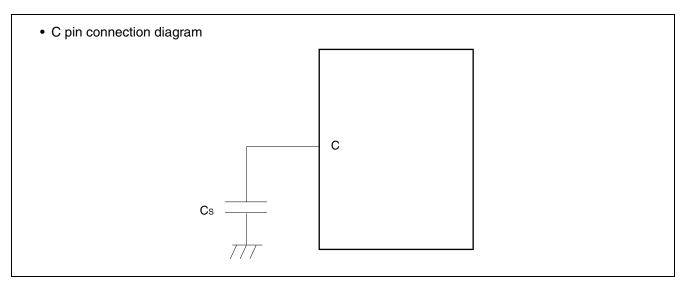
It is also advisable to connect a ceramic bypass capacitor of approximately 0.1 μF between V_{CC} and V_{SS} near this device.

• Mode Pin (MOD)

Connect the MOD pin directly to Vcc or Vss pins.

To prevent the device unintentionally entering test mode due to noise, lay out the printed circuit board so as to minimize the distance from the MOD pins to V_{CC} or V_{SS} pins and to provide a low-impedance connection.

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of $V_{\rm CC}$ pin must have a capacitance value higher than Cs. For connection of smoothing capacitor Cs, refer to the diagram below.



Analog Power Supply

Always set the same potential to AVcc and Vcc pins. When Vcc > AVcc, the current may flow through the AN00 to AN11 pins.

PROGRAMMING FLASH MEMORY MICROCONTROLLERS USING PARALLEL PROGRAMMER

• Supported Parallel Programmers and Adapters

The following table lists supported parallel programmers and adapters.

Package	Applicable adapter model	Parallel programmers
FPT-64P-M03	TEF110-108F35AP	AF9708 (Ver 02.35G or more)
FPT-64P-M09	TEF110-108F36AP	AF9709/B (Ver 02.35G or more) AF9723+AF9834 (Ver 02.08E or more)

Note : For information on applicable adapter models and parallel programmers, contact the following: Flash Support Group, Inc. TEL: +81-53-428-8380

Sector Configuration

The individual sectors of Flash memory correspond to addresses used for CPU access and programming by the parallel programmer as follows:

Flash memory	CPU address	Programmer address*	
SA1 (4 Kbytes)	<u>1000</u> н	71000н	
	1FFF _H	71FFFн	*
SA2 (4 Kbytes)	<u>2000</u> н	72000н	Lower bank
	2FFFH	72FFFн	Me
SA3 (4 Kbytes)	3000н	73000н	
(-))	3FFFH	73FFFH	
SA4 (16 Kbytes)	4000н	74000н	
	7FFFн	77FFFH	
SA5 (16 Kbytes)	8000н	78000 _H	
	BFFFH	7BFFFH	
SA6 (4 Kbytes)	Сооон	7С000н	춛
	CFFFH	7CFFFH	
SA7 (4 Kbytes)	D000н	7D000н	Upper bank
	DFFFH	7DFFFH	
SA8 (4 Kbytes)	Е000н	7E000н	
	EFFFH	7EFFFH	
SA9 (4 Kbytes)	F000H	7F000H	
	FFFFH	7 <u>FFFFh</u>	

These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

• Programming Method

- 1) Set the type code of the parallel programmer to "17222".
- 2) Load program data to programmer addresses 71000_H to 7FFFF_H.
- 3) Programmed by parallel programmer

Flash memory	CPU address	Programmer address*	
SA5 (16 Kbytes)	8000н	78000н	
	BFFFH	7BFFF _H	
SA6 (4 Kbytes)	С000н	7С000н	
	CFFFH	7CFFF _H	
SA7 (4 Kbytes)	D000н	7000н	
Gran (4 http://doi.org/	DFFFH	7DFFF _H	
SA8 (4 Kbytes)	<u>Е000</u> н	7Ē000н	
c/ ic (1 i ili j icc)	EFFFH	7EFFF _H	
SA9 (4 Kbytes)	— — <u></u> F 000н	7F000 _H	
SAB (4 NDyles)	FFFFH	7FFFF _H	

*: Programmer addresses are equivalent to CPU addresses, used when the parallel programmer programs data into Flash memory.

These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

• Programming Method

- 1) Set the type code of the parallel programmer to "17222"
- 2) Load program data to programmer addresses 78000 H to $7FFFF_{H}$.
- 3) Programmed by parallel programmer

• MB95F104AMS/F104ANS/F104AJS/F104AMW/F104ANW/F104AJW (16 Kbytes)

Flash memory	CPU address	Programmer address*
SA6 (4 Kbytes)	Сооон	7 <u>С000</u> н
	CFFF H	7CFFFн
SA7 (4 Kbytes)	D000н	7D000H
	DFFFH	7DFFFн
SA8 (4 Kbytes)	Е000н — — —	7Ē000 _H
	EFFFH	7EFFFн
SA9 (4 Kbytes)	F000H	7F000 _H
	FFF	7FFFF _H

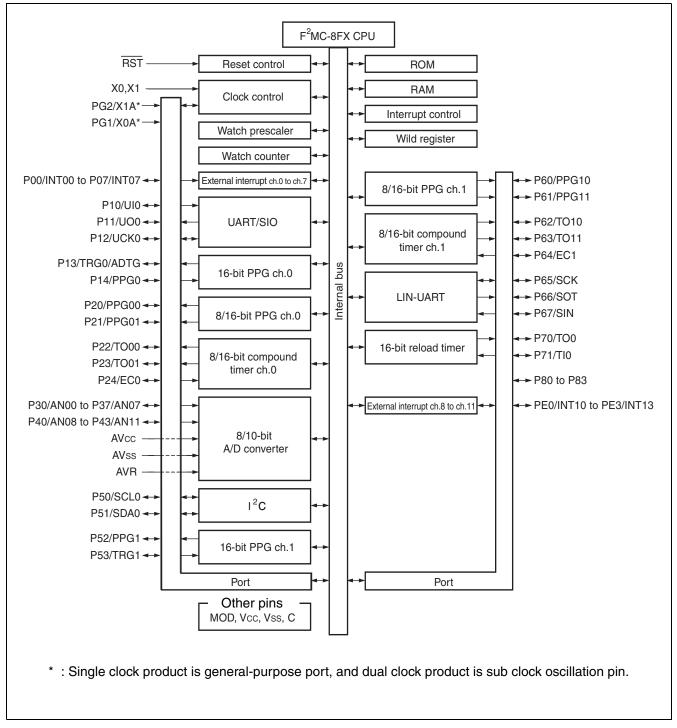
*: Programmer addresses are equivalent to CPU addresses, used when the parallel programmer programs data into Flash memory.

These programmer addresses are used for the parallel programmer to program or erase data in Flash memory.

• Programming Method

- 1) Set the type code of the parallel programmer to "17222"
- 2) Load program data to programmer addresses 7C000_H to 7FFFF_H.
- 3) Programmed by parallel programmer

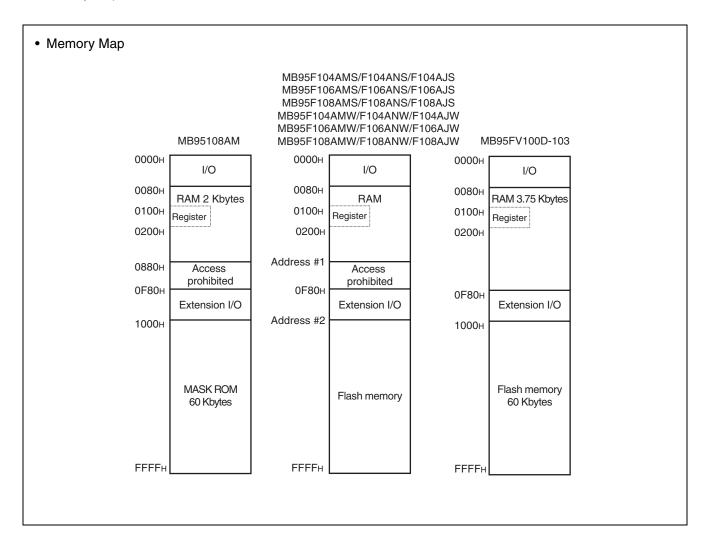
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory space

Memory space of the MB95100AM series is 64 Kbytes and consists of I/O area, data area, and program area. The memory space includes special-purpose areas such as the general-purpose registers and vector table. Memory map of the MB95100AM series is shown below.



	Flash	RAM	Address #1	Address #2	
MB95F104AMS/F104ANS/F104AJS	16 Kbytes	512 bytes	0280 _H	С000н	
MB95F104AMW/F104ANW/F104AJW	TO Ruyles	512 bytes	0200H	COOCH	
MB95F106AMS/F106ANS/F106AJS	22 Kbytaa	1 Kbyto	0480 _H	8000H	
MB95F106AMW/F106ANW/F106AJW	32 Kbytes	1 Kbyte	0400H	0000H	
MB95F108AMS/F108ANS/F108AJS	60 Khytaa	2 Khytaa	0880 _H	1000 _H	
MB95F108AMW/F108ANW/F108AJW	60 Kbytes	2 Kbytes	0000H	TUUUH	

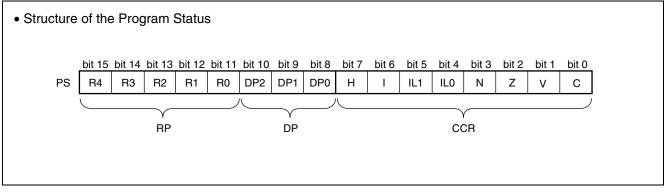
2. Register

The MB95100AM series has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The dedicated registers are as follows:

Program counter (PC)	: A 16-bit register to indicate locations where instructions are stored.
Accumulator (A)	: A 16-bit register for temporary storage of arithmetic operations. In the case of an 8-bit data processing instruction, the lower one byte is used.
Temporary accumulator (T)	: A 16-bit register which performs arithmetic operations with the accumulator. In the case of an 8-bit data processing instruction, the lower one byte is used.
Index register (IX)	: A 16-bit register for index modification.
Extra pointer (EP)	: A 16-bit pointer to point to a memory address.
Stack pointer (SP)	: A 16-bit register to indicate a stack area.
Program status (PS)	: A 16-bit register for storing a register bank pointer, a direct bank pointer, and a condition code register.

← 16-bit	: Program counter	Initial Value FFFD⊦
A	: Accumulator	0000н
Т	: Temporary accumulator	0000н
IX	: Index register	0000н
EP	: Extra pointer	0000н
SP	: Stack pointer	0000н
PS	: Program status	0030н

The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and a direct bank pointer (DP) and the lower 8 bits for use as a condition code register (CCR). (Refer to the diagram below.)



The RP indicates the address of the register bank currently being used. The relationship between the content of RP and the real address conforms to the conversion rule illustrated below:

Rule for Conversion of Actual Addresses in the General-purpose Register Area																
										RP upper		OP code lower				
	"0"	"0"	"0"	"0"	"0"	"0"	"0"	"1"	R4	R3	R2	R1	R0	b2	b1	b0
	•	¥	¥	¥	¥	¥	¥	¥	+	¥	¥	¥	¥	¥	¥	+
Generated address	A15	A14	A13	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0

The DP specifies the area for mapping instructions (16 different instructions such as MOV A, dir) using direct addresses to 0080^H to 00FF^H.

Direct bank pointer (DP2 to DP0)	Specified address area	Mapping area
XXX _B (no effect to mapping)	0000н to 007Fн	0000н to 007Fн (without mapping)
000 _B (initial value)		0080н to 00FFн (without mapping)
001в		0100н to 017Fн
010в		0180н to 01FFн
011в	0080н to 00FFн	0200н to 027Fн
100в		0280н to 02FFн
101в		0300н to 037Fн
110 _B		0380н to 03FFн
111 _B		0400н to 047Fн

The CCR consists of the bits indicating arithmetic operation results or transfer data contents and the bits that control CPU operations at interrupt.

- H flag : Set to "1" when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared to "0" otherwise. This flag is for decimal adjustment instructions.
- I flag : Interrupt is enabled when this flag is set to "1". Interrupt is disabled when this flag is set to "0". The flag is set to "0" when reset.
- IL1, IL0 : Indicates the level of the interrupt currently enabled. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	Priority
0	0	0	High
0	1	1	≜
1	0	2	ļ
1	1	3	Low = no interruption

N flag : Set to "1" if the MSB is set to "1" as the result of an arithmetic operation. Cleared to "0" when the bit is set to "0".

Z flag : Set to "1" when an arithmetic operation results in "0". Cleared to "0" otherwise.

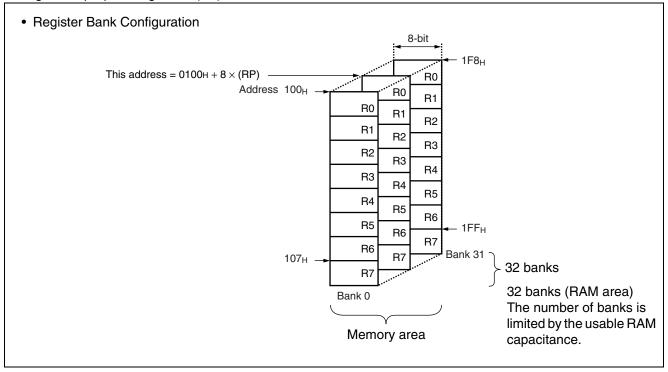
V flag : Set to "1" if the complement on 2 overflows as a result of an arithmetic operation. Cleared to "0" otherwise.

C flag : Set to "1" when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared to "0" otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: 8-bit data storage registers

The general-purpose registers are 8 bits and located in the register banks on the memory. 1-bank contains 8-registers. Up to a total of 32 banks can be used on the MB95100AM series. The bank currently in use is specified by the register bank pointer (RP), and the lower 3 bits of OP code indicates the general-purpose register 0 (R0) to general-purpose register 7 (R7).



■ I/O MAP

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001 н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н		(Disabled)		_
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111в
0006н	PLLC	PLL control register	R/W	0000000в
0007н	SYCC	System clock control register	R/W	1010X011 _B
0008 H	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R	XXXXXXXXB
000А н	TBTC	Timebase timer control register	R/W	0000000в
000Bн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	0000000в
000Dн		(Disabled)		
000Е н	PDR2	Port 2 data register	R/W	0000000в
000Fн	DDR2	Port 2 direction register	R/W	0000000в
0010 н	PDR3	Port 3 data register	R/W	0000000в
0011 н	DDR3	Port 3 direction register	R/W	0000000в
0012 н	PDR4	Port 4 data register	R/W	0000000в
0013 н	DDR4	Port 4 direction register	R/W	0000000в
0014 H	PDR5	Port 5 data register	R/W	0000000в
0015 H	DDR5	Port 5 direction register	R/W	0000000в
0016 H	PDR6	Port 6 data register	R/W	0000000в
0017 н	DDR6	Port 6 direction register	R/W	0000000в
0018 H	PDR7	Port 7 data register	R/W	0000000в
0019 н	DDR7	Port 7 direction register	R/W	0000000в
001А н	PDR8	Port 8 data register	R/W	0000000в
001B⊦	DDR8	Port 8 direction register	R/W	0000000в
001Сн to 0025н	_	(Disabled)	—	
0026н	PDRE	Port E data register	R/W	0000000в
0027н	DDRE	Port E direction register	R/W	0000000в
0028н, 0029н	_	(Disabled)	-	_
002А н	PDRG	Port G data register	R/W	0000000в

Address	Register abbreviation	Register name	R/W	Initial value
002Вн	DDRG	Port G direction register	R/W	0000000в
002Сн		(Disabled)		—
002Dн	PUL1	Port 1 pull-up register	R/W	0000000в
002Е н	PUL2	Port 2 pull-up register	R/W	0000000в
002Fн	PUL3	Port 3 pull-up register	R/W	0000000в
0030н	PUL4	Port 4 pull-up register	R/W	0000000в
0031н	PUL5	Port 5 pull-up register	R/W	0000000в
0032н	PUL7	Port 7 pull-up register	R/W	0000000в
0033н		(Disabled)		
0034н	PULE	Port E pull-up register	R/W	0000000в
00 35н	PULG	Port G pull-up register	R/W	0000000в
0036н	T01CR1	8/16-bit compound timer 01 control status register 1 ch.0	R/W	0000000в
0037н	T00CR1	8/16-bit compound timer 00 control status register 1 ch.0	R/W	0000000в
0038 H	T11CR1	8/16-bit compound timer 11 control status register 1 ch.1	R/W	0000000в
0039н	T10CR1	8/16-bit compound timer 10 control status register 1 ch.1	R/W	0000000в
003А н	PC01	8/16-bit PPG1 control register ch.0	R/W	0000000в
003Bн	PC00	8/16-bit PPG0 control register ch.0	R/W	0000000в
003Сн	PC11	8/16-bit PPG1 control register ch.1	R/W	0000000в
003Dн	PC10	8/16-bit PPG0 control register ch.1	R/W	0000000в
003Eн	TMCSRH0	16-bit reload timer control status register (Upper byte) ch.0	R/W	0000000в
003Fн	TMCSRL0	16-bit reload timer control status register (Lower byte) ch.0	R/W	0000000в
0040н, 0041н		(Disabled)	_	_
0042н	PCNTH0	16-bit PPG status control register (Upper byte) ch.0	R/W	0000000в
0043н	PCNTL0	16-bit PPG status control register (Lower byte) ch.0	R/W	0000000в
0044н	PCNTH1	16-bit PPG status control register (Upper byte) ch.1	R/W	0000000в
0045 н	PCNTL1	16-bit PPG status control register (Lower byte) ch.1	R/W	0000000в
0046н, 0047н		(Disabled)	_	_
0048н	EIC00	External interrupt circuit control register ch.0/ch.1	R/W	0000000в
0049 н	EIC10	External interrupt circuit control register ch.2/ch.3	R/W	0000000в
004Aн	EIC20	External interrupt circuit control register ch.4/ch.5	R/W	0000000в
004Bн	EIC30	External interrupt circuit control register ch.6/ch.7	R/W	0000000в
004Cн	EIC01	External interrupt circuit control register ch.8/ch.9	R/W	0000000в
004Dн	EIC11	External interrupt circuit control register ch.10/ch.11	R/W	0000000в

Address	Idress Register Register name		R/W	Initial value
004Ен, 004Fн		(Disabled)		_
0050н	SCR	LIN-UART serial control register	R/W	0000000в
0051 н	SMR	LIN-UART serial mode register	R/W	0000000в
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0053 н	RDR/TDR	LIN-UART reception/transmission data register	R/W	0000000в
0054 н	ESCR	LIN-UART extended status control register	R/W	00000100 _B
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XXE
0056н	SMC10	UART/SIO serial mode control register 1 ch.0	R/W	0000000B
0057 н	SMC20	UART/SIO serial mode control register 2 ch.0	R/W	0010000B
0058 н	SSR0	UART/SIO serial status register ch.0	R/W	0000001B
0059 н	TDR0	UART/SIO serial output data register ch.0	R/W	0000000E
005А н	RDR0	UART/SIO serial input data register ch.0	R	0000000
005Bн to 005Fн		(Disabled)	_	_
0060н	IBCR00	l ² C bus control register 0 ch.0	R/W	0000000
0061 н	IBCR10	I ² C bus control register 1 ch.0	R/W	0000000
0062н	IBSR0	I ² C bus status register ch.0	R	0000000E
0063 H	IDDR0	I ² C data register ch.0	R/W	0000000E
0064н	IAAR0	I ² C address register ch.0	R/W	0000000
0065 H	ICCR0	I ² C clock control register ch.0	R/W	0000000
0066н to 006Вн		(Disabled)	_	_
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000E
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000
006Eн	ADDH	8/10-bit A/D converter data register (Upper byte)	R/W	0000000
006Fн	ADDL	8/10-bit A/D converter data register (Lower byte)	R/W	0000000
0070н	WCSR	Watch counter status register	R/W	0000000
0071 н		(Disabled)		
0072н	FSR	Flash memory status register	R/W	000X000
0073н	SWRE0	Flash memory sector writing control register 0	R/W	0000000
0074н	SWRE1	Flash memory sector writing control register 1	R/W	0000000
0075н		(Disabled)		
0076н	WREN	Wild register address compare enable register	R/W	0000000
0077 н	WROR	Wild register data test setting register	R/W	0000000

Address	Register abbreviation	Register name	R/W	Initial value
0078н		Mirror of register bank pointer (RP) and direct bank pointer (DP)	_	
0079н	ILR0	Interrupt level setting register 0	R/W	11111111в
007Aн	ILR1	Interrupt level setting register 1	R/W	11111111
007Вн	ILR2	Interrupt level setting register 2	R/W	11111111
007Сн	ILR3	Interrupt level setting register 3	R/W	11111111в
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111
007Е н	ILR5	Interrupt level setting register 5	R/W	11111111
007Fн		(Disabled)		
0F80н	WRARH0	Wild register address setting register (Upper byte) ch.0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (Lower byte) ch.0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch.0	R/W	0000000в
0F83н	WRARH1	Wild register address setting register (Upper byte) ch.1	R/W	0000000в
0F84⊦	WRARL1	Wild register address setting register (Lower byte) ch.1	R/W	0000000в
0F85н	WRDR1	Wild register data setting register ch.1	R/W	0000000в
0F86н	WRARH2	Wild register address setting register (Upper byte) ch.2	R/W	0000000в
0F87н	WRARL2	Wild register address setting register (Lower byte) ch.2	R/W	0000000в
0F88н	WRDR2	Wild register data setting register ch.2	R/W	0000000в
0F89н to 0F91н	_	(Disabled)	_	_
0F92н	T01CR0	8/16-bit compound timer 01 control status register 0 ch.0	R/W	0000000в
0F93н	T00CR0	8/16-bit compound timer 00 control status register 0 ch.0	R/W	0000000в
0F94н	T01DR	8/16-bit compound timer 01 data register ch.0	R/W	0000000в
0F95н	T00DR	8/16-bit compound timer 00 data register ch.0	R/W	0000000в
0F96н	TMCR0	8/16-bit compound timer 00/01 timer mode control register ch.0	R/W	0000000в
0F97н	T11CR0	8/16-bit compound timer 11 control status register 0 ch.1	R/W	0000000в
0F98⊦	T10CR0	8/16-bit compound timer 10 control status register 0 ch.1	R/W	0000000в
0F99н	T11DR	8/16-bit compound timer 11 data register ch.1	R/W	0000000в
0F9Aн	T10DR	8/16-bit compound timer 10 data register ch.1	R/W	0000000в
0F9B⊦	TMCR1	8/16-bit compound timer 10/11 timer mode control register ch.1	R/W	0000000в
0F9Cн	PPS01	8/16-bit PPG1 cycle setting buffer register ch.0	R/W	11111111в
0F9DH	PPS00	8/16-bit PPG0 cycle setting buffer register ch.0	R/W	11111111в
0F9Eн	PDS01	8/16-bit PPG1 duty setting buffer register ch.0	R/W	11111111
0F9Fн	PDS00	8/16-bit PPG0 duty setting buffer register ch.0	R/W	11111111 1 в

Address	Register abbreviation	Register name	R/W	Initial value
0FA0н	PPS11	8/16-bit PPG1 cycle setting buffer register ch.1	R/W	11111111в
0FA1н	PPS10	8/16-bit PPG0 cycle setting buffer register ch.1	R/W	11111111в
0FA2н	PDS11	8/16-bit PPG1 duty setting buffer register ch.1	R/W	11111111в
0FA3⊦	PDS10	8/16-bit PPG0 duty setting buffer register ch.1	R/W	11111111в
0FA4⊦	PPGS	8/16-bit PPG start register	R/W	0000000в
0FA5н	REVC	8/16-bit PPG output inversion register	R/W	0000000в
0FA6⊦	TMRH0/ TMRLRH0	16-bit timer register (Upper byte) ch.0/ 16-bit reload register (Upper byte) ch.0	R/W	0000000в
0FA7н	TMRL0/ TMRLRL0	16-bit timer register (Lower byte) ch.0/ 16-bit reload register (Lower byte) ch.0	R/W	0000000в
0FA8н, 0FA9н		(Disabled)		_
0FAAH	PDCRH0	16-bit PPG down counter register (Upper byte) ch.0	R	0000000в
0FABH	PDCRL0	16-bit PPG down counter register (Lower byte) ch.0	R	0000000в
0FACH	PCSRH0	16-bit PPG cycle setting buffer register (Upper byte) ch.0	R/W	11111111B
0FADH	PCSRL0	16-bit PPG cycle setting buffer register (Lower byte) ch.0	R/W	11111111в
0FAEH	PDUTH0	16-bit PPG duty setting buffer register (Upper byte) ch.0	R/W	11111111в
0FAF _H	PDUTL0	16-bit PPG duty setting buffer register (Lower byte) ch.0	R/W	11111111
0FB0н	PDCRH1	16-bit PPG down counter register (Upper byte) ch.1	R	0000000в
0FB1н	PDCRL1	16-bit PPG down counter register (Lower byte) ch.1	R	0000000в
0FB2н	PCSRH1	16-bit PPG cycle setting buffer register (Upper byte) ch.1	R/W	11111111
0FB3н	PCSRL1	16-bit PPG cycle setting buffer register (Lower byte) ch.1	R/W	11111111в
0FB4н	PDUTH1	16-bit PPG duty setting buffer register (Upper byte) ch.1	R/W	11111111в
0FB5н	PDUTL1	16-bit PPG duty setting buffer register (Lower byte) ch.1	R/W	11111111в
0FB6н to 0FBBн		(Disabled)		_
0FBCH	BGR1	LIN-UART baud rate generator register 1	R/W	0000000в
0FBDH	BGR0	LIN-UART baud rate generator register 0	R/W	0000000в
0FBEH	PSSR0	UART/SIO dedicated baud rate generator prescaler selection register ch.0	R/W	0000000в
0FBF _H	BRSR0	UART/SIO dedicated baud rate generator baud rate setting register ch.0	R/W	0000000в
0FC0н, 0FC1н	_	(Disabled)		_
0FC2н	AIDRH	A/D input disable register (Upper byte)	R/W	0000000в
0FC3н	AIDRL	A/D input disable register (Lower byte)	R/W	0000000в

(Continued))			
Address	Register abbreviation	Register name	R/W	Initial value
0FC4н to 0FE2н		(Disabled)	_	—
0FE3⊦	WCDR	Watch counter data register	R/W	00111111в
0FE4н to 0FE6н	_	(Disabled)		_
0FE7н	ILSR2	Input level select register 2	R/W	0000000в
0FE8н, 0FE9н	_	(Disabled)	_	—
0FEAH	CSVCR	Clock supervisor control register	R/W	00011100в
0FEBн to 0FEDн	_	(Disabled)	_	—
0FEEH	ILSR	Input level select register	R/W	0000000в
0FEFH	WICR	Interrupt pin control register	R/W	0100000в
0FF0н to 0FFFн		(Disabled)	_	_

• R/W access symbols

- R/W : Readable/Writable
- R : Read only
- W : Write only

• Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.

Note : Do not write to the " (Disabled) ". Reading the " (Disabled) " returns an undefined value.

■ INTERRUPT SOURCE TABLE

	Interrupt	Vector tab	le address	Bit name of	Same level priority order (atsimultaneous occurrence)	
Interrupt source	request number	Upper	Lower	interrupt level setting register		
External interrupt ch.0	IRQ0	FFFAH	FFFBH	L00 [1 : 0]	High	
External interrupt ch.4						
External interrupt ch.1	IRQ1	FFF8 _H	FFF9⊦	L01 [1 : 0]		
External interrupt ch.5						
External interrupt ch.2	IRQ2	FFF6⊦	FFF7⊦	1.00.[1.0]		
External interrupt ch.6				L02 [1 : 0]		
External interrupt ch.3						
External interrupt ch.7	IRQ3	FFF4 _H	FFF5H	L03 [1 : 0]		
UART/SIO ch.0	IRQ4	FFF2H	FFF3H	L04 [1 : 0]		
8/16-bit compound timer ch.0 (Lower)	IRQ5	FFF0H	FFF1⊦	L05 [1 : 0]		
8/16-bit compound timer ch.0 (Upper)	IRQ6	FFEEH	FFEFH	L06 [1 : 0]		
LIN-UART (reception)	IRQ7	FFECH	FFEDH	L07 [1 : 0]		
LIN-UART (transmission)	IRQ8	FFEAH	FFEB H	L08 [1 : 0]		
8/16-bit PPG ch.1 (Lower)	IRQ9	FFE8H	FFE9H	L09 [1 : 0]		
8/16-bit PPG ch.1 (Upper)	IRQ10	FFE6H	FFE7н	L10 [1 : 0]		
16-bit reload timer ch.0	IRQ11	FFE4 _H	FFE5H	L11 [1 : 0]		
8/16-bit PPG ch.0 (Upper)	IRQ12	FFE2H	FFE3H	L12 [1 : 0]		
8/16-bit PPG ch.0 (Lower)	IRQ13	FFE0H	FFE1н	L13 [1 : 0]		
8/16-bit compound timer ch.1 (Upper)	IRQ14	FFDEH	FFDFH	L14 [1 : 0]		
16-bit PPG ch.0	IRQ15	FFDC _H	FFDDH	L15 [1 : 0]		
I ² C ch.0	IRQ16	FFDA H	FFDB H	L16 [1 : 0]		
16-bit PPG ch.1	IRQ17	FFD8H	FFD9н	L17 [1 : 0]		
8/10-bit A/D converter	IRQ18	FFD6н	FFD7н	L18 [1 : 0]		
Timebase timer	IRQ19	FFD4н	FFD5H	L19 [1 : 0]		
Watch prescaler/Watch counter	IRQ20	FFD2H	FFD3H	L20 [1 : 0]		
External interrupt ch.8						
External interrupt ch.9						
External interrupt ch.10	IRQ21	FFD0H	FFD1н	L21 [1 : 0]		
External interrupt ch.11						
8/16-bit compound timer ch.1 (Lower)	IRQ22	FFCEH	FFCFH	L22 [1 : 0]	▼	
Flash memory	IRQ23	FFCCH	FFCDH	L23 [1 : 0]	Low	

■ ELECTRICAL CHARACTERISTICS

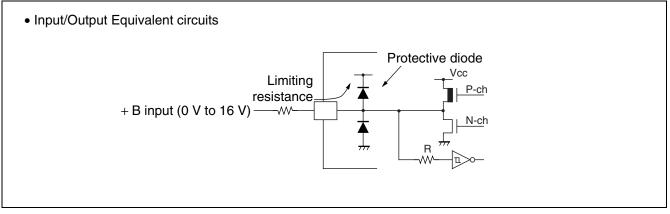
1. Absolute Maximum Ratings

Desemator	Symbol	Rating		Unit	Demorika		
Parameter	Symbol	Min	Max	Unit	Remarks		
Power supply voltage*1	Vcc AVcc	Vss - 0.3	Vss + 6.0	v	*2		
	AVR	Vss - 0.3	Vss + 6.0		*2		
Input voltage*1	Vı	Vss – 0.3	Vss + 6.0		*3		
Output voltage*1	Vo	Vss - 0.3	Vss + 6.0	V	*3		
Maximum clamp current	CLAMP	- 2.0	+ 2.0	mA	Applicable to pins*4		
Total maximum clamp current	Σ clamp	—	20	mA	Applicable to pins*4		
"L" level maximum	OL1		15	mA	Other than P00 to P07		
output current	OL2		15	IIIA	P00 to P07		
"L" level average	IOLAV1		4	mA	Other than P00 to P07 Average output current = operating current × operating ratio (1 pin)		
current	Iolav2		12		P00 to P07 Average output current = operating current × operating ratio (1 pin)		
"L" level total maximum output current	ΣΙοι	_	100	mA			
"L" level total average output current	ΣΙοιαν		50	mA	Total average output current = operating current × operating ratio (Total of pins)		
"H" level maximum	Іон1		– 15	A	Other than P00 to P07		
output current	Он2		– 15	mA	P00 to P07		
"H" level average	Iohav1		- 4	mA	Other than P00 to P07 Average output current = operating current × operating ratio (1 pin)		
current	Іонау2		- 8		P00 to P07 Average output current = operating current × operating ratio (1 pin)		
"H" level total maximum output current	ΣІон		- 100	mA			
"H" level total average output current	ΣΙοήαν		- 50	mA	Total average output current = operating current × operating ratio (Total of pins)		

(Continued)

Parameter	Symbol	Rat	Unit		
Farameter	Symbol	Min	Мах		
Power consumption	Pd	—	320	mW	
Operating temperature	Та	- 40	+ 85	°C	
Storage temperature	Tstg	- 55	+ 150	°C	

- *1 : The parameter is based on $AV_{SS} = V_{SS} = 0.0 V$.
- *2 : Apply equal potential to AVcc and Vcc. AVR should not exceed AVcc + 0.3 V.
- *3 : VI and Vo should not exceed Vcc + 0.3 V. VI must not exceed the rating voltage. However, if the maximum current to/from an input is limited by some means with external components, the IcLAMP rating supersedes the VI rating.
- *4 : Applicable to pins : P00 to P07, P10 to P14, P20 to P24, P30 to P37, P40 to P43, P52, P53, P70, P71, PE0 to PE3
 - Use within recommended operating conditions.
 - Use at DC voltage (current).
 - +B signal is an input signal that exceeds Vcc voltage. The + B signal should always be applied a limiting resistance placed between the + B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the + B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input
 potential may pass through the protective diode and increase the potential at the Vcc pin, and this affect
 other devices.
 - Note that if the + B signal is inputted when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the + B input is applied during power-on, the power supply is provided from the pins and the resulting power supply voltage may not be sufficient to operate the power-on reset.
 - Care must be taken not to leave the + B input pin open.
 - Sample recommended circuits :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

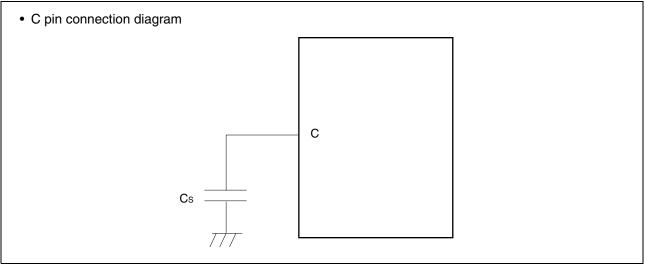
2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Sym-	Pin name	Condi- tions	Value		Unit	Remarks		
raiameter	bol			Min	Max	Unit	neillaiks		
Power	Vcc, AVcc			2.42*1	5.5	V	At normal operating		
				2.3	5.5		Retain status of stop operation	Other than MB95FV100D-103	
supply voltage				2.7	5.5		At normal operating		
				2.3	5.5		Retain status of stop operation	MB95FV100D-103	
A/D converter reference input voltage	AVR	_		4.0	AVcc	v			
Smoothing capacitor	Cs			0.1	1.0	μF	*2		
Operating	T۸	Та —		- 40	+ 85	°C	Other than MB95FV100D-103		
temperature	TA			+ 5	+ 35		MB95FV100D-103		

*1: The value is 2.88 V when the low voltage detection reset is used.

*2 : Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. A bypass capacitor of V_{CC} pin must have a capacitance value higher than C_S. For connection of smoothing capacitor C_S, refer to the diagram below.



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

3. DC Characteristics

Value Sym-Parameter Pin name Conditions Unit Remarks bol Min Тур Max Hysteresis Vcc + Vін P10, P50, P51, P67 *1 0.7 Vcc V input of CMOS 0.3 input level P00 to P07, P10 to P14, P20 to P24, P30 to P37, Pin input at P40 to P43, P50 to P53, selecting of V VIHA 0.8 Vcc Vcc + 0.3P60 to P67, P70, P71, Automotive P80 to P83, PE0 to PE3, input level PG1*2, PG2*2 "H" level input P00 to P07, P10 to P14, voltage P20 to P24, P30 to P37, P40 to P43, P50 to P53, Vcc + VIHS *1 0.8 Vcc V Hysteresis input P60 to P67, P70, P71, 0.3 P80 to P83, PE0 to PE3, PG1*2, PG2*2 CMOS input (MASK ROM Vcc + RST, MOD V 0.7 Vcc product is VIHM 0.3 hysteresis input) Hysteresis Vss -P10, P50, P51, P67 *1 0.3 Vcc V input of CMOS Vı∟ 0.3 input level P00 to P07, P10 to P14, P20 to P24, P30 to P37, Pin input at P40 to P43, P50 to P53, selecting of VILA Vss - 0.30.5 Vcc V P60 to P67, P70, P71, Automotive P80 to P83, PE0 to PE3, input level PG1*2, PG2*2 "L" level input P00 to P07. P10 to P14. voltage P20 to P24, P30 to P37, P40 to P43, P50 to P53, Vss -VILS *1 0.2 Vcc Hysteresis input ٧ P60 to P67, P70, P71, 0.3 P80 to P83, PE0 to PE3, PG1*2, PG2*2 CMOS input (MASK ROM Vss -RST, MOD 0.3 Vcc V product is VILM 0.3 hysteresis input)

(Vcc = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 °C to + 85 °C)

_	Sym-				Value	•		
Parameter	bol	Pin name	Conditions	Min	Тур	Max	Unit	Remarks
Open-drain output application voltage	VD	P50, P51, P80 to P83		Vss – 0.3		Vss + 5.5	v	
"H" level output	V _{OH1}	Output pin other than P00 to P07	Іон = – 4.0 mA	V _{cc} – 0.5	v			
voltage	V _{OH2}	P00 to P07	Іон = – 8.0 mA	V _{cc} – 0.5	_		V	
"L" level output	V _{OL1}	Output pin other than P00 to P07, RST*3	lo∟ = 4.0 mA		_	0.4	V	
voltage	V _{OL2}	P00 to P07	lo∟ = 12 mA			0.4	V	
Input leakage current (Hi-Z output leakage current)	lu	Port other than P50, P51, P80 to P83	0.0 V < Vı < Vcc	- 5		+ 5	μA	When the pull-up prohibition setting
Open-drain output leakage current		P50, P51, P80 to P83	0.0 V < Vı < Vss + 5.5 V			5	μA	
Pull-up resistor	Rpull	P10 to P14,P20 to P24, P30 to P37, P40 to P43, P52, P53, P70, P71, PE0 to PE3, PG1* ² , PG2* ²	Vı = 0.0 V	25	50	100	kΩ	When the pull-up permission setting
Pull-down resistor	RMOD	MOD	VI = Vcc	25	50	100	kΩ	MASK ROM product
Input capacitance	CIN	Other than AVcc, AVss, AVR, Vcc, Vss	f = 1 MHz		5	15	pF	
			Vcc = 5.5 V Fcн = 20 MHz		9.5	12.5	mA	Flash memory product (At other than writing and erasing)
			$F_{MP} = 10 \text{ MHz}$ Main clock mode (divided by 2)		30	35	mA	Flash memory product (At writing and erasing)
Power supply	lac	Vcc (External clock			7.2	9.5	mA	MASK ROM product
current*4	lcc		Fсн = 32 MHz Fмp = 16 MHz		15.2	20.0	mA	Flash memory product (At other than writing and erasing)
			Main clock mode (divided by 2)		35.7	42.5	mA	Flash memory product (At writing and erasing)
				—	11.6	15.2	mA	MASK ROM product (Continued)

(Vcc = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 $^{\circ}C$ to + 85 $^{\circ}C)$

(Continued)

Demonstern	ameter Sym- Pin name		O an dition a		Value		11	Doworka
Parameter	bol	Pin name	Conditions	Min	Тур	Max	Unit	Remarks
	Iccs		$V_{CC} = 5.5 V$ $F_{CH} = 20 MHz$ $F_{MP} = 10 MHz$ Main sleep mode (divided by 2)		4.5	7.5	mA	
			$F_{CH} = 32 \text{ MHz}$ $F_{MP} = 16 \text{ MHz}$ Main sleep mode (divided by 2)		7.2	12.0	mA	
IccL IccLs Power supply		$\begin{split} V_{CC} &= 5.5 \ V \\ F_{CL} &= 32 \ kHz \\ F_{MPL} &= 16 \ kHz \\ Sub \ clock \ mode \\ (divided \ by \ 2) \ , \\ T_A &= \ + \ 25 \ ^{\circ}C \end{split}$	_	45	100	μΑ	Dual clock product only	
	Vcc (External clock			10	81	μA	Dual clock product only	
current*4	Ісст	operation)	$V_{CC} = 5.5 V$ $F_{CL} = 32 kHz$ Watch mode Main stop mode $T_A = +25 \ ^{\circ}C$		4.6	27.0	μA	Dual clock product only
			$V_{CC} = 5.5 V$ $F_{CH} = 4 MHz$		9.3	12.5	mA	Flash memory product
	ICCMPLL		F _{MP} = 10 MHz Main PLL mode (multiplied by 2.5)		7.0	9.5	mA	MASK ROM product
			Fсн = 6.4 MHz Fм₽ = 16 MHz		14.9	20.0	mA	Flash memory product
			Main PLL mode (multiplied by 2.5)		11.2	15.2	mA	MASK ROM product
			$\begin{split} V_{CC} &= 5.5 \ V \\ F_{CL} &= 32 \ kHz \\ F_{MPL} &= 128 \ kHz \\ Sub \ PLL \ mode \\ (multiplied \ by \ 4) \ , \\ T_A &= \ + \ 25 \ ^\circ C \end{split}$		160	400	μA	Dual clock product only

(Vcc = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = $\,-$ 40 $^{\circ}C$ to $\,+$ 85 $^{\circ}C$)

(Continued)

(Continued)

 $(Vcc = AVcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

Demoster	Sym-	Diagonal	O and this and		Value			Describe
Parameter	bol	Pin name	Conditions	Min	Тур	Max	Unit	Remarks
Іссн	Істѕ	Vcc (External clock	$V_{CC} = 5.5 V$ $F_{CH} = 10 MHz$ Timebase timer mode $T_A = +25 \ ^{\circ}C$		0.15	1.10	mA	
	operation)	$V_{CC} = 5.5 V$ Sub stop mode $T_A = +25 \text{ °C}$		3.5	20	μΑ	Main stop mode for single clock product	
	Ilvd	Vcc	Current consumption for low voltage detection circuit only		38	50	μΑ	
Power supply current*4	lcsv	VCC	At oscillating 100 kHz current consumption of internal CR oscillator		20	36	μΑ	
	la		$V_{CC} = 5.5 V$ $F_{CH} = 16 MHz$ At operating of A/D conversion		2.4	4.7	mA	
	Іан	AVcc	$V_{CC} = 5.5 V$ $F_{CH} = 16 MHz$ At stopping A/D conversion $T_A = +25 \ ^{\circ}C$		1	5	μΑ	

*1: P10, P50, P51, and P67 can switch the input level to either the "CMOS input level" or "hysteresis input level". The switching of the input level can be set by the input level selection register (ILSR).

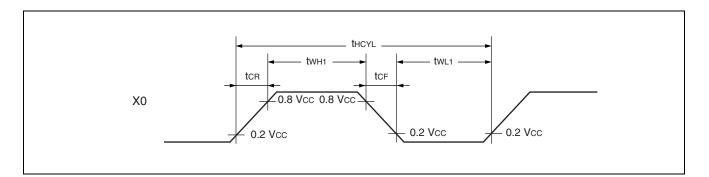
- *2 : Single clock products only
- *3 : Product without clock supervisor only
- *4: The power-supply current is determined by the external clock. When the low voltage detection option is selected, the power-supply current will be a value of adding current consumption of the low voltage detection circuit (I_{LVD}) to the specified value. Also, when both low voltage detection option and clock supervisor are selected, the power-supply current will be a value of adding current consumption of the low voltage detection circuit (I_{LVD}) and current consumption of internal CR oscillator (I_{CSV}) to the specified value.
 - Refer to "4. AC Characteristics (1) Clock Timing" for FCH and FCL.
 - Refer to "4. AC Characteristics (2) Source Clock/Machine Clock" for FMP and FMPL.

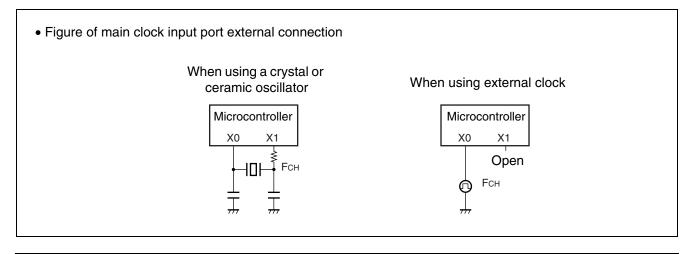
4. AC Characteristics

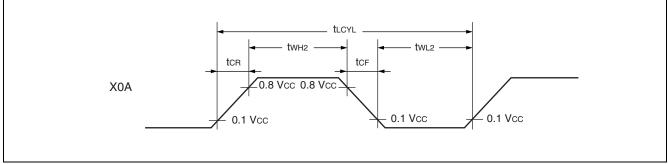
(1) Clock Timing

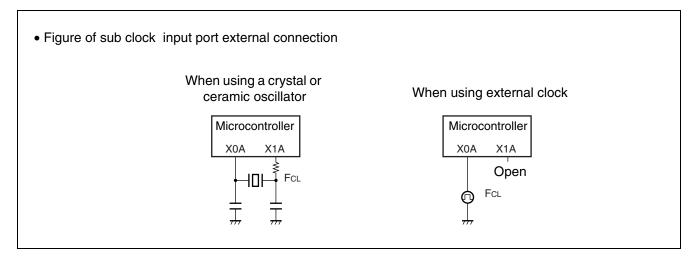
	1	,				$v_{33} = 0.0 v, TA = -40 0 t0 + 00$		
Parameter	Sym-	Pin name	Condi-		Value		Unit	Remarks
i di dificici	bol	r in name	tions	Min	Тур	Мах	Onic	Temarks
				1.00		16.25	MHz	When using main oscillation circuit
Clock frequency	_			1.00		32.50	MHz	When using external clock
	Fсн	X0, X1		3.00		10.00	MHz	Main PLL multiplied by 1
				3.00		8.13	MHz	Main PLL multiplied by 2
				3.00		6.50	MHz	Main PLL multiplied by 2.5
	Fc∟	X0A, X1A			32.768		kHz	When using sub oscillation circuit
					32.768		kHz	When using sub PLL
	t HCYL	X0, X1	_	61.5	_	1000	ns	When using oscillation circuit
Clock cycle time				30.8		1000	ns	When using external clock
	t LCYL	X0A, X1A			30.5		μs	When using sub clock
Input clock pulse width	twнı tw∟ı	X0		61.5	_		ns	When using external clock Duty ratio is about 30% to
Input clock pulse width	twн₂ tw∟₂	X0A			15.2		μs	70%.
Input clock rise time and fall time	tcr tcr	X0, X0A				5	ns	When using external clock

$(Vcc = 2.42 V to 5.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$







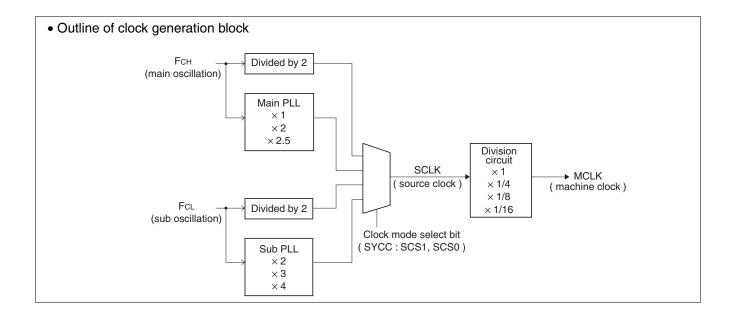


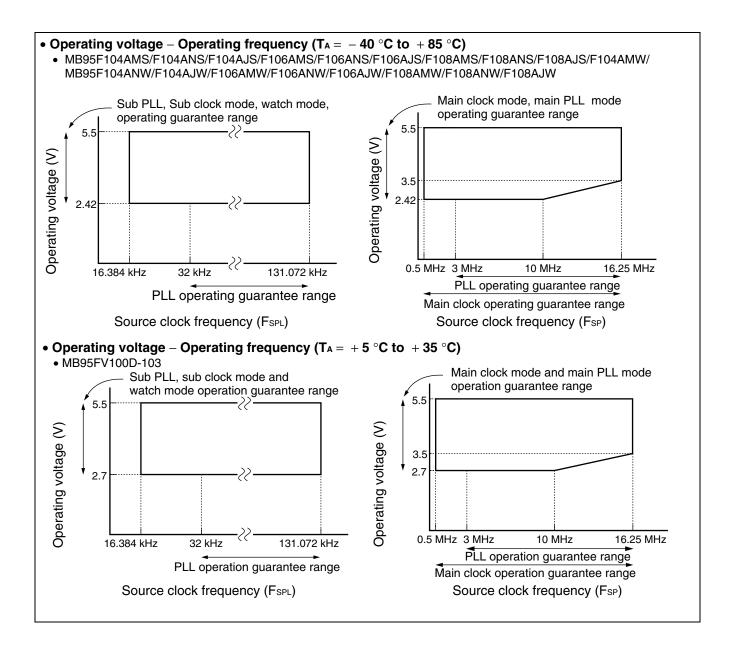
(2) Source Clock/Machine Clock

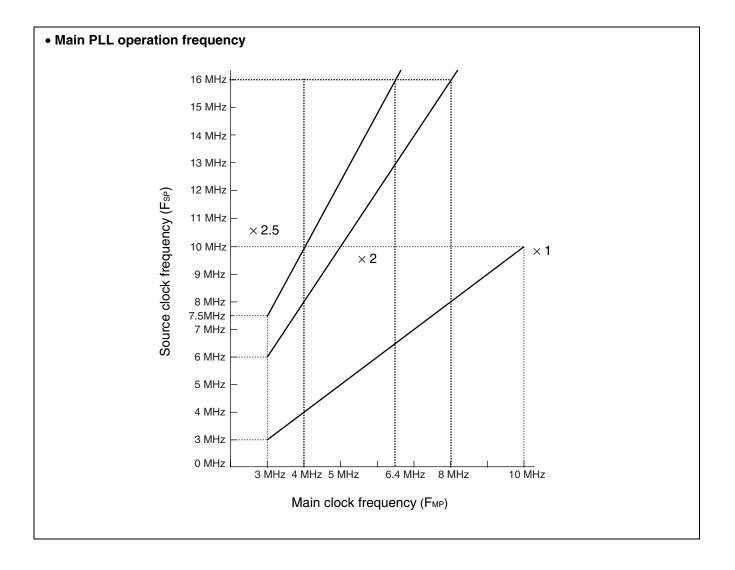
 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 \circ C to + 85 \circ C)$ Value Pin Sym-Parameter Unit Remarks bol name Max Min Тур When using main clock Min : Fcн = 16.25 MHz, 61.5 2000 ns PLL multiplied by 1 Source clock*1 Max : $F_{CH} = 1$ MHz, divided by 2 (Clock before setting **t**SCLK division) When using sub clock 61.0 Min : $F_{CL} = 32$ kHz, PLL multiplied by 4 7.6 μs Max : $F_{CL} = 32$ kHz, divided by 2 Fsp 0.50 16.25 MHz When using main clock Source clock frequency FSPL 16.384 131.072 kHz When using sub clock When using main clock 61.5 32000 Min : $F_{SP} = 16.25$ MHz, no division ns Machine clock*2 Max : $F_{SP} = 0.5$ MHz, divided by 16 (Minimum instruction **t**MCLK When using sub clock execution time) 976.5 Min : $F_{SPL} = 131 \text{ kHz}$, no division 7.6 μs Max : $F_{SPL} = 16$ kHz, divided by 16 MHz When using main clock 0.031 16.250 Machine clock Fмр ____ frequency kHz When using sub clock FMPL 1.024 131.072

*1 : Clock before setting division due to machine clock division ratio selection bit (SYCC : DIV1 and DIV0) . This source clock is divided by the machine clock division ratio selection bit (SYCC : DIV1 and DIV0) , and it becomes the machine clock. Further, the source clock can be selected as follows.

- Main clock divided by 2
- PLL multiplication of main clock (select from 1, 2, 2.5 multiplication)
- Sub clock divided by 2
- PLL multiplication of sub clock (select from 2, 3, 4 multiplication)
- *2 : Operation clock of the microcontroller. Machine clock can be selected as follows.
 - Source clock (no division)
 - Source clock divided by 4
 - Source clock divided by 8
 - Source clock divided by 16







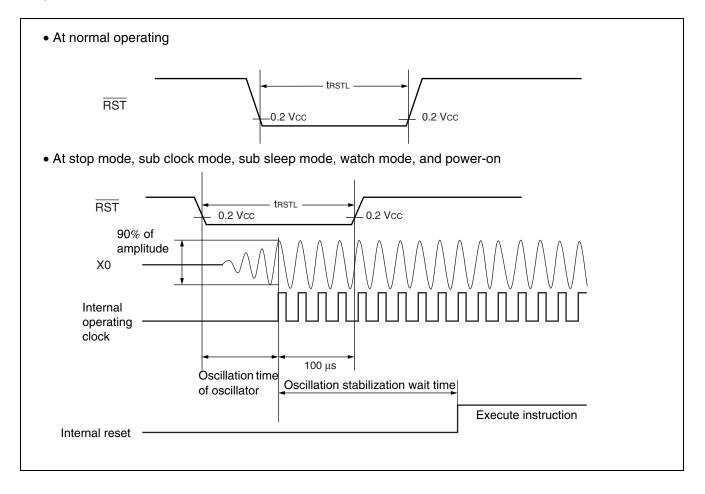
(3) External Reset

	$(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 \circ C to + 85 \circ C)$									
Parameter	Symbol	Value	Value		Remarks					
Farameter	Symbol	Min	Max	Unit	nemarks					
		2 tмськ*1		ns	At normal operating					
RST "L" level pulse width	t RSTL	Oscillation time of oscillator*2 + 100	_	μs	At stop mode, sub clock mode, sub sleep mode, and watch mode					
		100		μs	At timebase timer mode					

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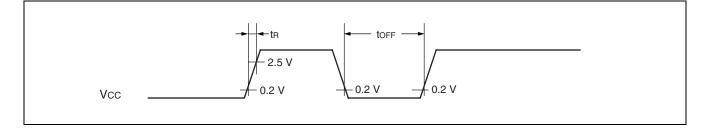
*1 : Refer to " (2) Source Clock/Machine Clock" for tmclk.

*2 : Oscillation time of oscillator is the time that the amplitude reaches 90 %. In the crystal oscillator, the oscillation time is between several ms and tens of ms. In ceramic oscillators, the oscillation time is between hundreds of μs and several ms. In the external clock, the oscillation time is 0 ms.

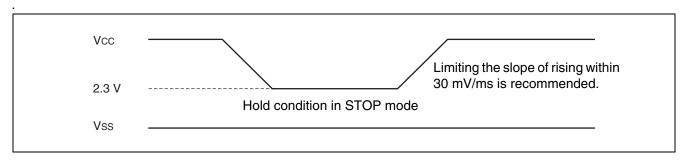


(4) Power-on Reset

$(AVss = Vss = 0.0 V, T_A = -40 \degree C to + 85 \degree C$										
Parameter	Symbol	Conditions	Va	lue	Unit	Remarks				
Faialletei	Symbol	Conditions	Min	Max	Unit	neillaiks				
Power supply rising time	tR	_		50	ms					
Power supply cutoff time	toff		1		ms	Waiting time until power-on				



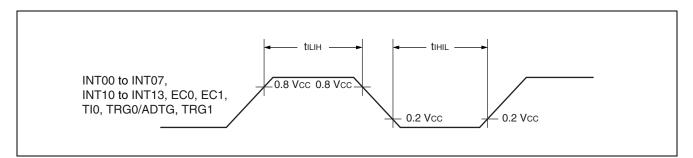
Note : Sudden change of power supply voltage may activate the power-on reset function. When changing power supply voltages during operation, set the slope of rising within 30 mV/ms as shown below



(5) Peripheral Input Timing

$(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 \degree C to + 85$										
Parameter	Symbol	Pin name	Va	Unit						
Parameter	Symbol	Fill liallie	Min	Max	Unit					
Peripheral input "H" pulse width	tіцін	INT00 to INT07, INT10 to INT13,	2 t мськ*	_	ns					
Peripheral input "L" pulse width	tініL	EC0, EC1, TI0, TRG0/ADTG, TRG1	2 t мськ*		ns					

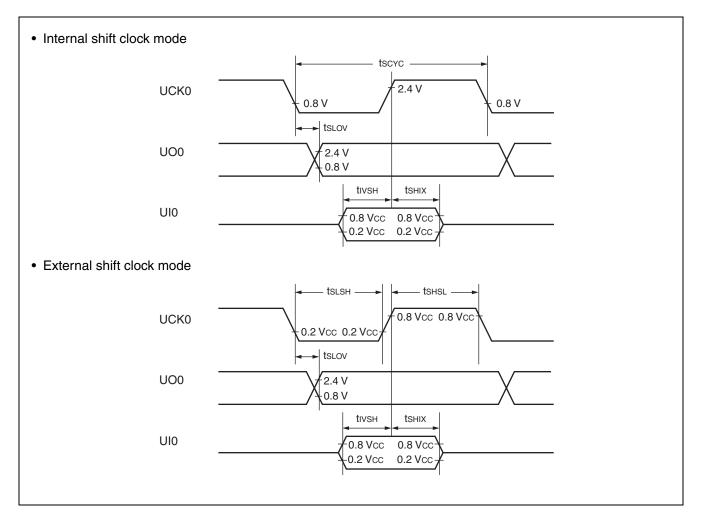
*: Refer to "(2) Source Clock/Machine Clock" for tmclk.



(6) UART/SIO, Serial I/O Timing

(,, , , , , , , , , , , , , , , , , , ,		$(Vcc = 5.0 V \pm 10)$	0%, AVss = Vss	s = 0.0 V, TA =	= − 40 °C to	+ 85 °C)
Parameter	Symbol	Pin name	Conditions	Va	Unit	
i didiletei	Symbol	rinname	Conditions	Min	Max	onit
Serial clock cycle time	tscyc	UCK0		4 tmclk*	—	ns
UCK $\downarrow \rightarrow$ UO time	tslov	UCK0, UO0	Internal clock	- 190	+ 190	ns
Valid UI \rightarrow UCK \uparrow	tıvsн	UCK0, UI0	operation	2 t MCLK*	_	ns
UCK $\uparrow \rightarrow$ valid UI hold time	tshix	UCK0, UI0		2 t MCLK*	_	ns
Serial clock "H" pulse width	tshsl	UCK0		4 tmclk*	_	ns
Serial clock "L" pulse width	tslsh	UCK0	External	4 t MCLK*	_	ns
$UCK\downarrow \to UO$ time	tslov	UCK0, UO0	clock		190	ns
Valid UI \rightarrow UCK \uparrow	tıvsн	UCK0, UI0	operation	2 t MCLK*	_	ns
UCK $\uparrow \rightarrow$ valid UI hold time	tsнıx	UCK0, UI0		2 t MCLK*		ns

* : Refer to " (2) Source Clock/Machine Clock" for tmclk.



(7) LIN-UART Timing

Sampling at the rising edge of sampling clock*1 and prohibited serial clock delay*2

(ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

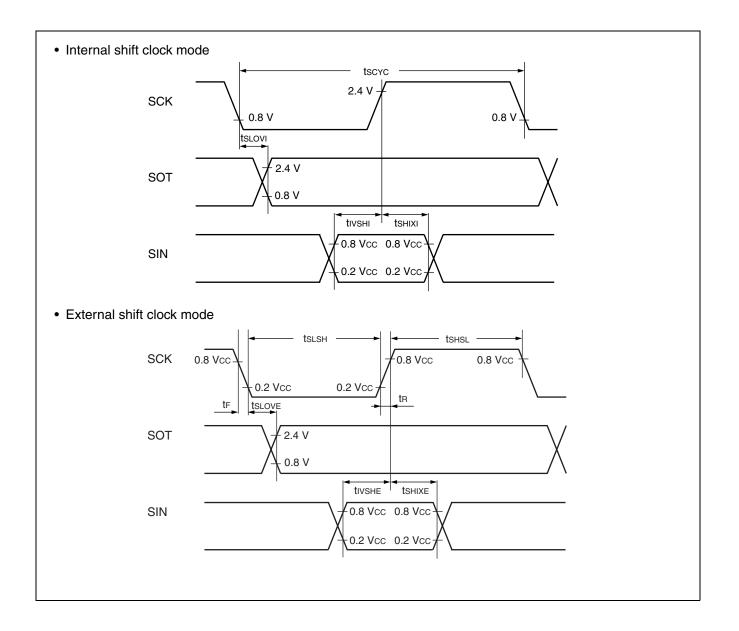
(Vcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 °C to + 85 °C)

Parameter	Sym-	Pin name	Conditions	Va	lue	Unit
Falailletei	bol	Fininanie	Conditions	Value Min Max 5 tmcLk*3 — -95 +95 tmcLk*3 + 190 — 0 — 3 tmcLk*3 - tR — tmcLk*3 + 95 — 2 tmcLk*3 + 95 — 190 — tmcLk*3 + 95 — 190 — 10 —	Unit	
Serial clock cycle time	tscyc	SCK		5 t мськ* ³		ns
$SCK \downarrow \to SOT$ delay time	tslovi	SCK, SOT	operation output pin :	- 95	+ 95	ns
$Valid\ SIN \to SCK\ \uparrow$	tivshi	SCK, SIN		tмськ*3 + 190		ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tshixi	SCK, SIN		0		ns
Serial clock "L" pulse width	tslsh	SCK		$3 t$ MCLK $^{*3} - t$ R	_	ns
Serial clock "H" pulse width	tsнs∟	SCK		t мськ*3 + 95		ns
$SCK \downarrow \to SOT$ delay time	t SLOVE	SCK, SOT	External clock	_	2 tмськ*3 + 95	ns
$Valid\ SIN \to SCK\ \uparrow$	tivshe	SCK, SIN	operation output pin :	190	_	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tshixe	SCK, SIN	C∟ = 80 pF + 1 TTL.	tмськ*3 + 95		ns
SCK fall time	t⊧	SCK			10	ns
SCK rise time	tR	SCK		_	10	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to " (2) Source Clock/Machine Clock" for tmclk.



Sampling at the falling edge of sampling clock^{*1} and prohibited serial clock delay^{*2}

(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

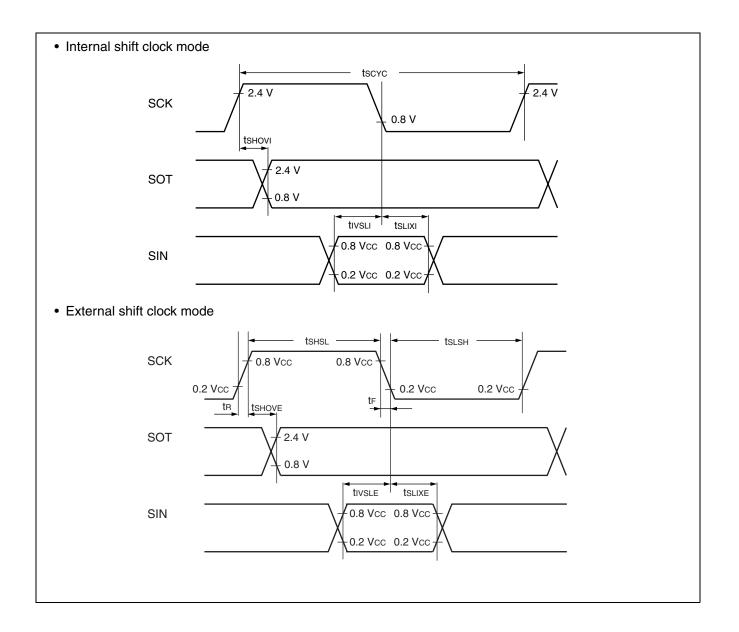
 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 \circ C to + 85 \circ C)$

Parameter	Sym- Pin name		Conditions	Va	lue	Unit
Faidilletei	bol	Fininanie	Conditions	$\frac{t_{MCLK}^{*3} + 190}{0} - \frac{-}{0}$ $\frac{3 t_{MCLK}^{*3} - t_{R}}{t_{MCLK}^{*3} + 95} - \frac{-}{2}$ $\frac{-}{2 t_{MCLK}^{*3} + 95} - \frac{-}{0}$ $\frac{-}{10} t_{MCLK}^{*3} + 95 - \frac{-}{0}$	Max	Unit
Serial clock cycle time	tscyc	SCK		5 t мclk ^{*3}	—	ns
$SCK \uparrow \to SOT \text{ delay time}$	t shovi	SCK, SOT	operation output pin : $C_{L} = 80 \text{ pF} + 1 \text{ TTL}.$	- 95	+ 95	ns
$Valid\:SIN\toSCK\:\downarrow$	tivsli	SCK, SIN		tмськ* ³ + 190	—	ns
$SCK \downarrow \to valid \ SIN \ hold \ time$	ts∟ıxı	SCK, SIN		0	—	ns
Serial clock "H" pulse width	tsнs∟	SCK		$3 t$ мськ $^{*3} - t$ в	—	ns
Serial clock "L" pulse width	t s∟sн	SCK		tмськ* ³ + 95	—	ns
$SCK \uparrow \to SOT \text{ delay time}$	t shove	SCK, SOT	External clock	_	2 t мськ* ³ + 95	ns
$Valid\:SIN\toSCK\:\downarrow$	tivsle	SCK, SIN	operation output pin :	190	—	ns
$SCK \downarrow \to valid \ SIN \ hold \ time$	tslixe	SCK, SIN	C∟ = 80 pF + 1 TTL.	tмськ*3 + 95	—	ns
SCK fall time	t⊧	SCK			10	ns
SCK rise time	tR	SCK		_	10	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to " (2) Source Clock/Machine Clock" for tmclk.



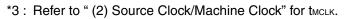
Sampling at the rising edge of sampling clock*1 and enabled serial clock delay*2

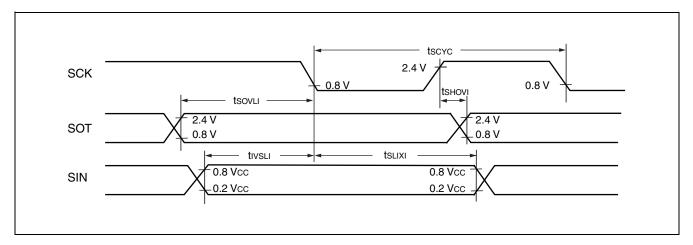
(ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

		(Vcc	= 5.0 V ± 10%, AVss = 1	$Vss = 0.0 V, T_A$	$= -40 \ ^{\circ}\text{C}$ to	+ 85 °C)
Parameter	Sym-		Conditions	Val	Unit	
Faidilielei	bol	Pin name	Conditions	Min	Max	Onit
Serial clock cycle time	tscyc	SCK		5 t MCLK ^{*3}		ns
$SCK \uparrow \to SOT \text{ delay time}$	t shovi	SCK, SOT	Internal clock	- 95	+ 95	ns
$Valid\;SIN\toSCK\;\!\downarrow$	tivsli	SCK, SIN	operation output pin :	tмськ*3 + 190		ns
$SCK \downarrow \rightarrow valid \ SIN \ hold \ time$	tslixi	SCK, SIN	C∟ = 80 pF + 1 TTL.	0		ns
$SOT \to SCK \downarrow delay time$	tsovu	SCK, SOT			4 t мськ* ³	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.





Sampling at the falling edge of sampling clock^{*1} and enabled serial clock delay^{*2}

(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

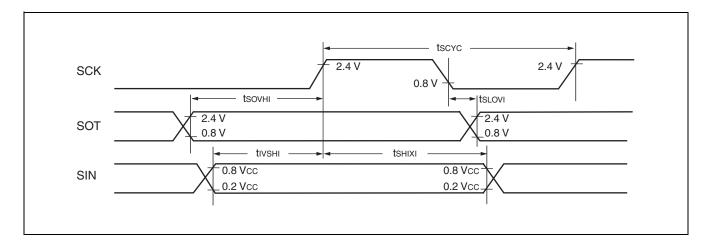
 $(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 \circ C to + 85 \circ C)$

Parameter	Sym-	Pin name	Conditions	Valu	Unit	
Falameter	bol	Finnanie	Conditions	Min	/alue Max + 95 00 4 t _{MCLK} *3	Onit
Serial clock cycle time	tscyc	SCK		5 t MCLK ^{*3}	_	ns
$SCK \downarrow \to SOT \text{ delay time}$	tslovi	SCK, SOT	Internal clock	- 95	+ 95	ns
Valid SIN \rightarrow SCK \uparrow	tivshi	SCK, SIN	operating output pin :	tмськ*3 + 190		ns
$SCK \uparrow \to valid \; SIN \; hold \; time$	tshixi	SCK, SIN	C∟ = 80 pF + 1 TTL.	0		ns
$SOT \to SCK \uparrow delay time$	tsovнi	SCK, SOT			4 t MCLK* ³	ns

*1 : Provide switch function whether sampling of reception data is performed at rising edge or falling edge of the serial clock.

*2 : Serial clock delay function is used to delay half clock for the output signal of serial clock.

*3 : Refer to " (2) Source Clock/Machine Clock" for tmclk.



(8) I²C Timing

	(/ ± 10%, AVss =		Val		• •• •	
Parameter	Symbol	Pin name	Conditions		dard- ode	Fast-	Unit	
				Min	Max	Min	Max	
SCL clock frequency	fsc∟	SCL0		0	100	0	400	kHz
(Repeat) Start condition hold time SDA $\downarrow \rightarrow$ SCL \downarrow	t hd;sta	SCL0 SDA0		4.0		0.6		μs
SCL clock "L" width	tLOW	SCL0		4.7		1.3		μs
SCL clock "H" width	tніgн	SCL0		4.0		0.6		μs
(Repeat) Start condition setup time SCL $\uparrow \rightarrow$ SDA \downarrow	tsu;sta	SCL0 SDA0	R = 1.7 kΩ,	4.7		0.6		μs
Data hold time SCL $\downarrow \rightarrow$ SDA $\downarrow \uparrow$	thd;dat	SCL0 SDA0	$C = 50 \text{ pF}^{*1}$	0	3.45* ²	0	0.9* ³	μs
Data setup time SDA $\downarrow \uparrow \rightarrow$ SCL \uparrow	t su;dat	SCL0 SDA0		0.25	_	0.1		μs
Stop condition setup time SCL $\uparrow \rightarrow$ SDA \uparrow	tsu;sto	SCL0 SDA0		4		0.6		μs
Bus free time between stop condition and start condition	tBUF	SCL0 SDA0		4.7		1.3		μs

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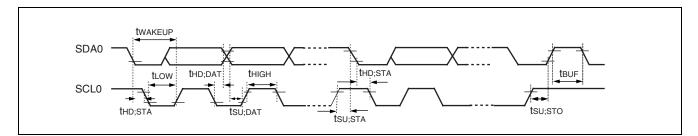
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*1 : R, C : Pull-up resistor and load capacitor of the SCL and SDA lines.

*2 : The maximum the;DAT have only to be met if the device dose not stretch the "L" width (tLOW) of the SCL signal.

*3 : A Fast-mode l²C-bus device can be used in a Standard-mode l²C-bus system, but the requirement $t_{SU;DAT} \ge 250$ ns must then be met.



Demonster	Sym-	Pin	O a m aliti a m	Valu	le*2	11	Demoster
Parameter	bol	name	Condition	Min	Max	Unit	Remarks
SCL clock "L" width	tLOW	SCL0		(2 + nm / 2) t _{MCLK} - 20		ns	Master mode
SCL clock "H" width	tнigн	SCL0		(nm / 2) tмськ – 20	(nm / 2) tмськ + 20	ns	Master mode
Start condition hold time	thd;sta	SCL0 SDA0		(—1 + nm / 2) tмськ — 20	(−1 + nm) t _{MCLK} + 20	ns	Master mode Maximum value is applied when m, $n = 1, 8$. Otherwise, the minimum value is applied.
Stop condition setup time	t su;sто	SCL0 SDA0		(1 + nm / 2) t _{MCLK} - 20	(1 + nm / 2) t _{MCLK} + 20	ns	Master mode
Start condition setup time	tsu;sta	SCL0 SDA0		(1 + nm / 2) t _{MCLK} - 20	(1 + nm / 2) t _{MCLK} + 20	ns	Master mode
Bus free time between stop condition and start condition	tbuf	SCL0 SDA0		(2 nm + 4) t _{MCLK} – 20		ns	
Data hold time	t hd;dat	SCL0 SDA0		3 tмськ – 20		ns	Master mode
Data setup time	tsu;dat	SCL0 SDA0	R = 1.7 kΩ, C = 50 pF*1	(-2 + nm / 2) tмськ – 20	(−1 + nm / 2) t _{MCLK} + 20	ns	Master mode When assuming that "L" of SCL is not extended, the minimum value is applied to first bit of continuous data. Otherwise, the maximum value is applied.
Setup time between clearing interrupt and SCL rising	tsu;int	SCL0		(nm / 2) t _{MCLK} – 20	(1 + nm / 2) t _{MCLK} + 20	ns	Minimum value is applied to interrupt at 9th SCL \downarrow . Maximum value is applied to interrupt at 8th SCL \downarrow .
SCL clock "L" width	t∟ow	SCL0		4 tмськ – 20	—	ns	At reception
SCL clock "H" width	tніgн	SCL0		4 tmclk - 20		ns	At reception
Start condition detection	t hd;sta	SCL0 SDA0		2 t _{MCLK} – 20		ns	Undetected when 1 tmclk is used at reception
Stop condition detection	t su;sто	SCL0 SDA0		2 tmclk – 20	_	ns	Undetected when 1 tmclk is used at reception
Restart detection condition	tsu;sta	SCL0 SDA0		2 t _{MCLK} – 20	_	ns	Undetected when 1 tmclk is used at reception
Bus free time	t BUF	SCL0 SDA0		2 tmclk - 20		ns	At reception
Data hold time	t hd;dat	SCL0 SDA0		2 tmclk - 20		ns	At slave transmission mode
Data setup time	t su;dat	SCL0 SDA0		$t_{\text{LOW}} - 3 t_{\text{MCLK}} - 20$	_	ns	At slave transmission mode

(Vcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = - 40 °C to + 85 °C)

(Continued)

(Continued)

$(Vcc = 5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40 \degree C to +85$								
Parameter	Sym-	Pin	Condition	Value* ²			Remarks	
Farameter	bol	name	Condition	Min	Мах	Unit	nemarks	
Data hold time	t hd;dat	SCL0 SDA0		0	_	ns	At reception	
Data setup time	tsu;dat	SCL0 SDA0	R = 1.7 kΩ, C = 50 pF*1	tмськ — 20		ns	At reception	
SDA↓→SCL↑ (at wake-up function)	twakeup	SCL0 SDA0		Oscillation stabilization wait time + 2 tмськ – 20	_	ns		

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*1 : R, C : Pull-up resistor and load capacitor of the SCL and SDA lines.

*2 : • Refer to " (2) Source Clock/Machine Clock" for tmclk.

- m is CS4 bit and CS3 bit (bit 4 and bit 3) of clock control register (ICCR0) .
- n is CS2 bit to CS0 bit (bit 2 to bit 0) of clock control register (ICCR0).
- Actual timing of I²C is determined by m and n values set by the machine clock (t_{MCLK}) and CS4 to CS0 of ICCR0 register.
- Standard-mode :

m and n can be set at the range : $0.9 \text{ MHz} < t_{\text{MCLK}}$ (machine clock) < 10 MHz. Setting of m and n limits the machine clock that can be used below.

• Fast-mode :

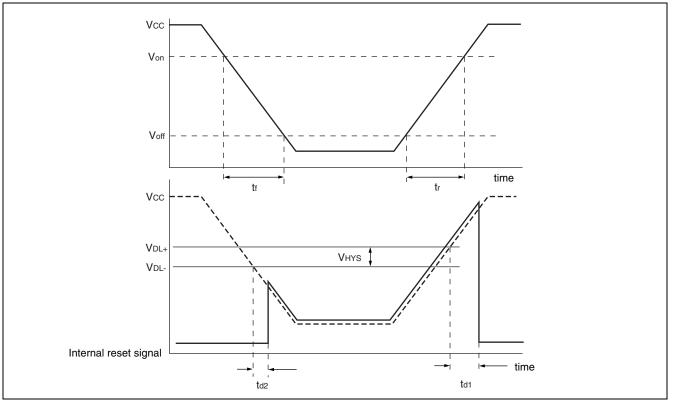
m and n can be set at the range : 3.3 MHz < $t_{\mbox{MCLK}}$ (machine clock) < 10 MHz.

Setting of m and n limits the machine clock that can be used below. (m, n) = (1, 8) : 3.3 MHz < t_{MCLK} \leq 4 MHz

(9) Low Voltage Detection

(AVss = Vss = 0.0 V, $T_A = -40 \ ^\circ C$ to $+ 85 \ ^\circ C$)

Parameter	Symbol		Value		Unit	Remarks
Parameter	Symbol	Min	Тур	Max	Unit	nemarks
Release voltage	V _{DL+}	2.52	2.70	2.88	V	At power-supply rise
Detection voltage	Vdl-	2.42	2.60	2.78	V	At power-supply fall
Hysteresis width	VHYS	70	100		mV	
Power-supply start voltage	Voff			2.3	V	
Power-supply end voltage	Von	4.9			V	
Power-supply voltage		0.3		_	μs	Slope of power supply that reset release signal generates
change time (at power supply rise)	tr -		3000		μs	Slope of power supply that reset release signal generates within rating (V_{DL+})
Power-supply voltage		300			μs	Slope of power supply that reset detection signal generates
change time (at power supply fall)	tr	_	300	_	μs	Slope of power supply that reset detection signal generates within rating (V _{DL-})
Reset release delay time	t _{d1}			400	μs	
Reset detection delay time	t _{d2}			30	μs	
Current consumption	Ilvd		38	50	μA	Current consumption for low voltage detection circuit only



(10) Clock Supervisor Clock

$(VCC = AVCC = 5.0 V \pm 10\%, AVSS = VSS = 0.0 V, IA = -40 C t0 + 60$								
Parameter	Symbol		Value		Unit	Remarks		
Farameter	Symbol	Min	Тур	Max	Unit	nelliaiks		
Oscillation frequency	fouт	50	100	200	kHz			
Oscillation start time	t _{wk}			10	μs			
Current consumption	lcsv		20	36	μA	Current consumption of built-in CR oscillator, at oscillation of 100 kHz		

(Vcc = AVcc = 5.0 V \pm 10%, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

5. A/D Converter

(1) A/D Converter Electrical Characteristics

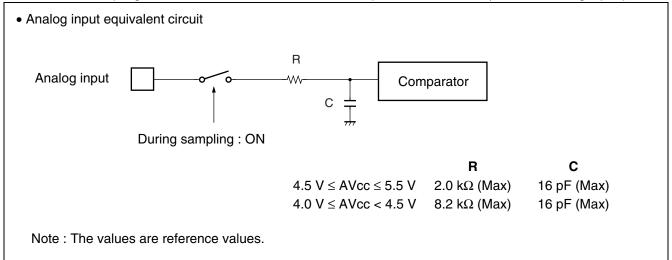
 $(AVcc = Vcc = 4.0 V to 5.5 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

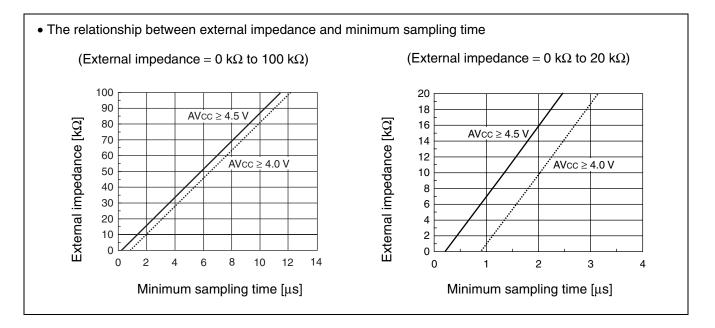
Parameter	Cumbal		Value	Unit	Remarks	
Parameter	Symbol	Min Typ Max		Max	Unit	Remarks
Resolution				10	bit	
Total error		- 3.0		+ 3.0	LSB	
Linearity error		- 2.5	—	+ 2.5	LSB	
Differential linear error		- 1.9		+ 1.9	LSB	
Zero transition voltage	Vот	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	V	
Full-scale transition voltage	VFST	AVR – 3.5 LSB	AVR – 1.5 LSB	AVR + 0.5 LSB	V	
Compare time		0.9		16500	μs	$4.5 \text{ V} \le \text{AVcc} \le 5.5 \text{ V}$
Compare ume		1.8		16500	μs	$4.0 \text{ V} \le \text{AVcc} < 4.5 \text{ V}$
Complianting		0.6	_	œ	μs	$\begin{array}{l} \text{4.5 V} \leq \text{AVcc} \leq 5.5 \text{ V},\\ \text{At external impedance} < \\ \text{5.4 k} \Omega \end{array}$
Sampling time		1.2		∞	μs	$4.0 V \le AVcc < 4.5 V$, At external impedance < $2.4 k\Omega$
Analog input current	Iain	- 0.3		+ 0.3	μA	
Analog input voltage	VAIN	AVss		AVR	V	
Reference voltage	—	AVss + 4.0	_	AVcc	V	AVR pin
Reference voltage	IR		600	900	μA	AVR pin, During A/D operation
supply current	Івн	_		5	μA	AVR pin, At stop mode

(2) Notes on Using A/D Converter

• About the external impedance of analog input and its sampling time

A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, consider the relationship between the external impedance and minimum sampling time and either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. Also, if the sampling time cannot be sufficient, connect a capacitor of about 0.1 μ F to the analog input pin.





About errors

As IAVR - AVssI becomes smaller, values of relative errors grow larger.

(3) Definition of A/D Converter Terms

Resolution

The level of analog variation that can be distinguished by the A/D converter.

When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

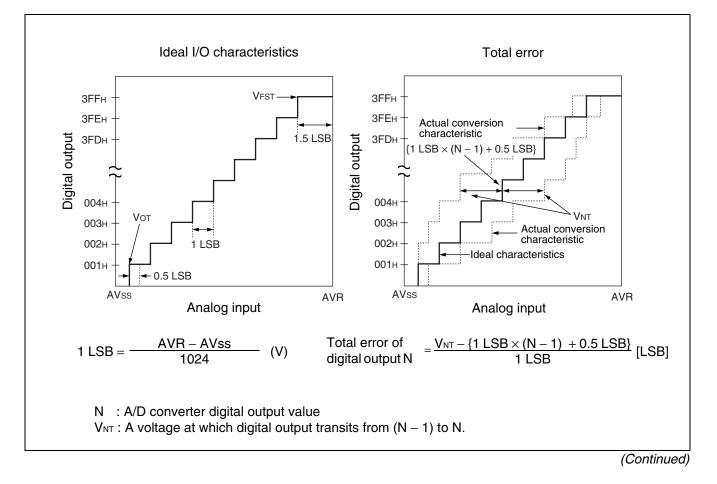
• Linearity error (unit : LSB)

The deviation between the value along a straight line connecting the zero transition point ("00 0000 0000" \leftarrow \rightarrow "00 0000 0001") of a device and the full-scale transition point ("11 1111 1111" \leftarrow \rightarrow "11 1111 1110") compared with the actual conversion values obtained.

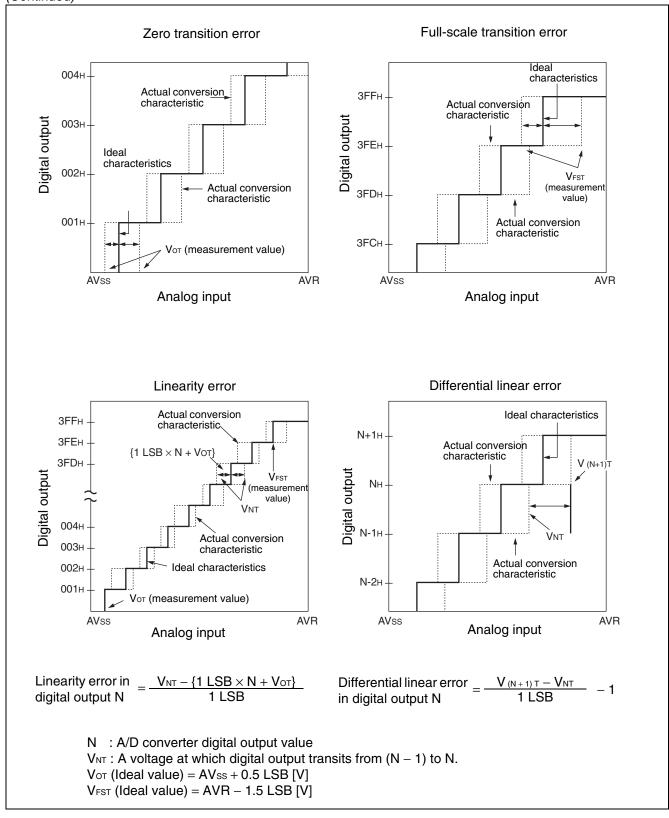
• Differential linear error (Unit : LSB) Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.

• Total error (unit: LSB)

Difference between actual and theoretical values, caused by a zero transition error, full-scale transition error, linearity error, quantum error, and noise.



(Continued)



Parameter		Value		Unit	Remarks
Falailletei	Min	Тур	Max	Unit	nelliaiks
Sector erase time (4 Kbytes sector)	_	0.2*1	0.5* ²	S	Excludes 00H programming prior erasure.
Sector erase time (16 Kbytes sector)		0.5* ¹	7.5* ²	S	Excludes 00H programming prior erasure.
Byte programming time	_	32	3,600	μs	Excludes system-level overhead.
Erase/program cycle	10000	_		cycle	
Power supply voltage at erase/ program	4.5		5.5	V	
Flash memory data retention time	20* ³			year	Average T _A = +85 °C

6. Flash Memory Program/Erase Characteristics

*1 : $T_{\text{A}}=~+~25~^{\circ}\text{C},~V_{\text{CC}}=5.0$ V, 10000 cycles

*2 : $T_{\text{A}}=$ + 85 °C, Vcc = 4.5 V, 10000 cycles

*3 : This value comes from the technology qualification (using Arrhenius equation to translate high temperature measurements into normalized value at +85 °C) .

■ MASK OPTION

No.	Part number	MB95108AM	MB95F104AMS MB95F104ANS MB95F104AJS MB95F106AMS MB95F106AJS MB95F108AMS MB95F108ANS MB95F108AJS	MB95F104AMW MB95F104ANW MB95F104AJW MB95F106AMW MB95F106AJW MB95F108AMW MB95F108ANW MB95F108ANW	MB95FV100D-103
	Specifying procedure	Specify when ordering MASK	Setting disabled	Setting disabled	Setting disabled
1	Clock mode select • Single-system clock mode • Dual-system clock mode	Selectable	Single-system clock mode	Dual-system clock mode	Changing by the switch on MCU board
2	Low voltage detection reset* • With low voltage detection reset • Without low voltage detection reset	Specify when ordering MASK	Specified by part number	Specified by part number	Changing by the switch on MCU board
3	Clock supervisor* • With clock supervisor • Without clock supervisor	Specify when ordering MASK	Specified by part number	Specified by part number	Changing by the switch on MCU board
4	Reset output* • With reset output • Without reset output	Specify when ordering MASK	Specified by part number	Specified by part number	 MCU board switch set as following ; With supervisor : Without reset output Without supervisor : With reset output
5	Oscillation stabilization wait time	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /F _{CH}	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /Fсн	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /F _{CH}	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /Fсн

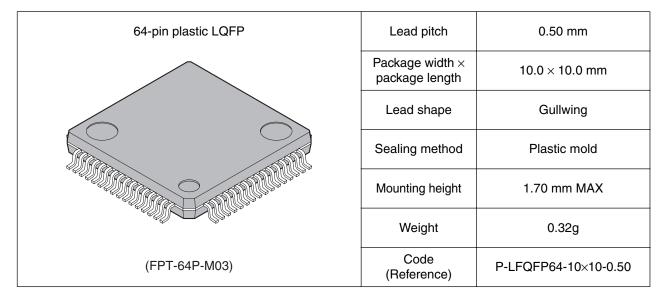
*: Refer to table below about clock mode select, low voltage detection reset, clock supervisor select and reset output.

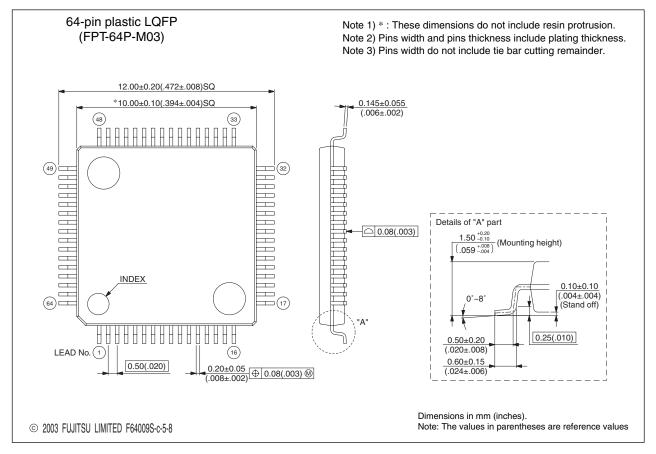
Part number	Clock mode select	Low voltage detection reset	Clock supervisor	Reset output
		No	No	Yes
	Single-system	Yes	No	Yes
MB95108AM		Yes	Yes	No
WID95106AW		No	No	Yes
	Dual-system	Yes	No	Yes
		Yes	Yes	No
MB95F104AMS		No	No	Yes
MB95F104ANS		Yes	No	Yes
MB95F104AJS		Yes	Yes	No
MB95F106AMS		No	No	Yes
MB95F106ANS	Single-system	Yes	No	Yes
MB95F106AJS		Yes	Yes	No
MB95F108AMS		No	No	Yes
MB95F108ANS		Yes	No	Yes
MB95F108AJS		Yes	Yes	No
MB95F104AMW		No	No	Yes
MB95F104ANW		Yes	No	Yes
MB95F104AJW		Yes	Yes	No
MB95F106AMW		No	No	Yes
MB95F106ANW	Dual-system	Yes	No	Yes
MB95F106AJW		Yes	Yes	No
MB95F108AMW		No	No	Yes
MB95F108ANW		Yes	No	Yes
MB95F108AJW	1	Yes	Yes	No
		No	No	Yes
	Single-system	Yes	No	Yes
MB95FV100D-103		Yes	Yes	No
IVID90FV100D-103		No	No	Yes
	Dual-system	Yes	No	Yes
		Yes	Yes	No

■ ORDERING INFORMATION

Part number	Package
MB95108AMPFV MB95F104AMSPFV/F104ANSPFV/F104AJSPFV MB95F104AMWPFV/F104ANWPFV/F104AJWPFV MB95F106AMSPFV/F106ANSPFV/F106AJSPFV MB95F106AMWPFV/F106ANWPFV/F106AJWPFV MB95F108AMSPFV/F108ANSPFV/F108AJSPFV MB95F108AMWPFV/F108ANWPFV/F108AJWPFV	64-pin plastic LQFP (FPT-64P-M03)
MB95108AMPFM MB95F104AMSPFM/F104ANSPFM/F104AJSPFM MB95F104AMWPFM/F104ANWPFM/F104AJWPFM MB95F106AMSPFM/F106ANSPFM/F106AJSPFM MB95F106AMWPFM/F106ANWPFM/F106AJWPFM MB95F108AMSPFM/F108ANSPFM/F108AJSPFM MB95F108AMWPFM/F108ANWPFM/F108AJWPFM	64-pin plastic LQFP (FPT-64P-M09)
MB2146-303 (MB95FV100D-103PBT)	MCU board (224-pin plastic PFBGA (BGA-224P-M08))

PACKAGE DIMENSIONS

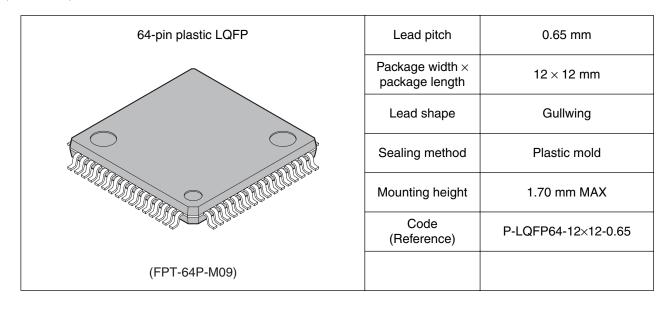


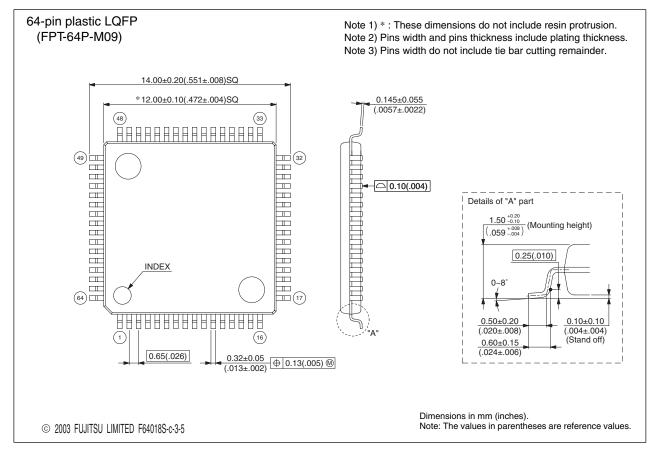


Please confirm the latest Package dimension by following URL. http://edevice.fujitsu.com/fj/DATASHEET/ef-ovpklv.html

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■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results		
_		Added the part numbers. (MB95F104AJS/MB95F104AJW MB95F106AJS/MB95F106AJW MB95F108AJS/MB95F108AJW)		
4	■ PRODUCT LINEUP	Added the description "Clock supervisor" in the section "Option".		
18	■ PROGRAMMING FLASH MEMORY MICROCONTROLLERS USING PARALLEL PROGRAMMER	Inserted " • Programming Method".		
31	■ I/O MAP	Added the address 0FEAH.		
		"Verified the Min value in the section of "Other than MB95FV100D-103", "In normal operating" of "Power supply voltage"; 2.45 \rightarrow 2.42.		
35	2. Recommended Operating Conditions	Verified the value in *1; 2.9 V \rightarrow 2.88 V.		
		Moved "H" level input voltage and "L" level input voltage to the section "3. DC Characteristics".		
36		Added the pin name at the "Pin name" in the section of V_{IHA} , "H" level input voltage.		
30	3. DC Characteristics	Added the pin name at the "Pin name" in the section of V_{ILA} , "L" level input voltage.		
39		Deleted the line of " $F_{CH} = 16$ MHz" in the section " I_{CTS} " of Power supply current.		
	4 AC Characteristics	Changed in the table; Vcc = 2.5 V to 5.5 V \rightarrow Vcc = 2.42 V to 5.5 V.		
40	4. AC Characteristics (1) Clock Timing	Changed the Max value on the third column of the clock frequency; $16.25 \rightarrow 10.00$		
45	4. AC Characteristics(2) Source Clock/Machine Clock	Verified the diagram of Main PLL operation frequency range.		
50	(Q) Low Voltage Detection	Changed the release voltage: $2.55 \rightarrow 2.52$ (Min value) $2.85 \rightarrow 2.88$ (Max value)		
59	(9) Low Voltage Detection	Changed the detection voltage: $2.45 \rightarrow 2.42$ (Min value) $2.75 \rightarrow 2.78$ (Max value)		

The information for microcontroller supports is shown in the following homepage. http://www.fujitsu.com/global/services/microelectronics/product/micom/support/index.html

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